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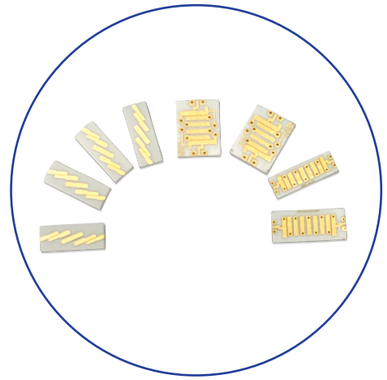
Yun Micro Electronics

Yun Micro Electronics Ltd. (China)

-----Customizable Microwave RF Filters



Film Filter

Yun Micro Electronics

CONTENTS

Catalog

Catalog

IYFTB2200-900-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

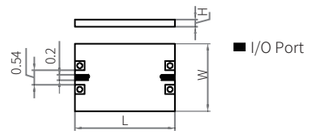
Environmental Parameters

Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

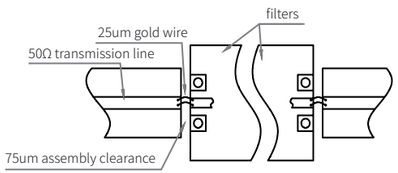
	Min	Typical	Max	
Center Freq	-	2.2	-	GHz
Band Freq	1.75	-	2.65	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@1.45GHz			
	⩾40dB@2.95GHz			

Overall Dimensions

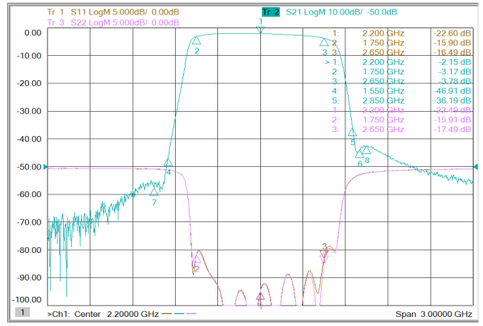


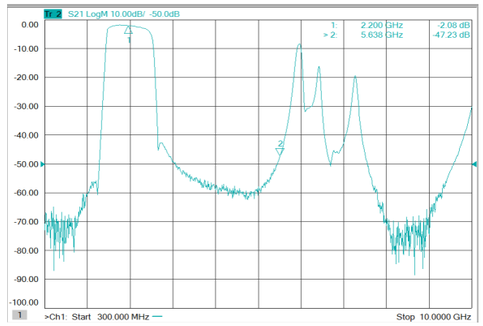
notation	value	unit
L	8.6	mm
W	9.8	mm
H	0.381	mm

Suggested Assembly Drawings



Typical Curve





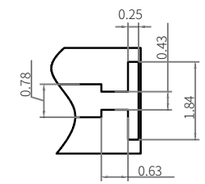
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

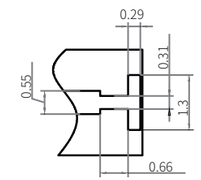
2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz



Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB3050-200-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

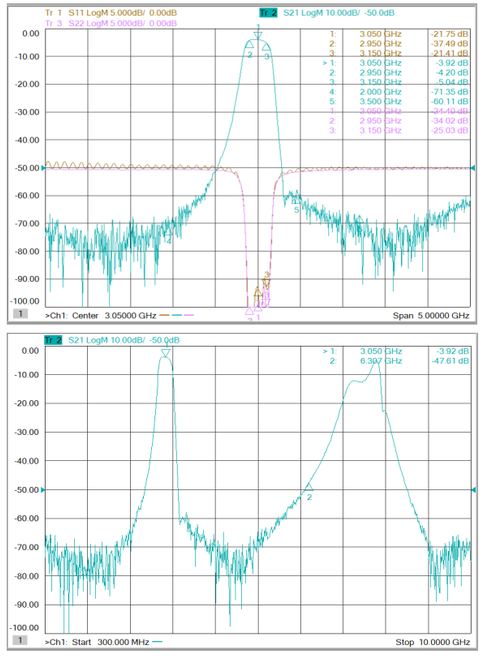
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	3.05	-	GHz
Band Freq	2.95	-	3.15	GHz
Fc IL	-	4.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@2 GHz			
	⩾40dB@3.5 GHz			

Typical Curve



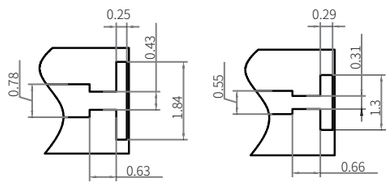
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

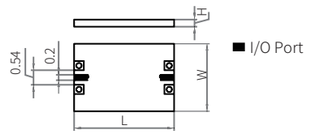


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

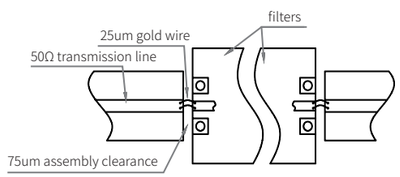
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.0	mm
W	9.0	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB3150-800-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

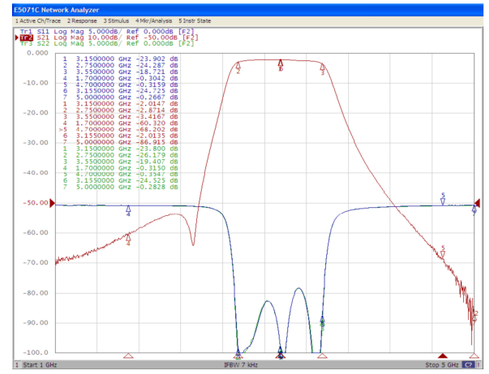
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	3.15	-	GHz
Band Freq	2.75	-	3.55	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@2.2 GHz			
	⩾40dB@4.6 GHz			

Typical Curve



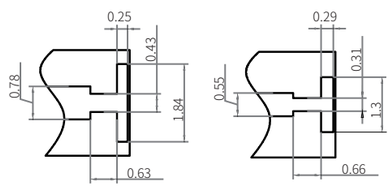
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

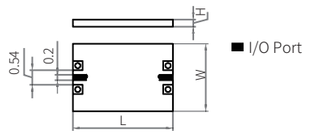


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

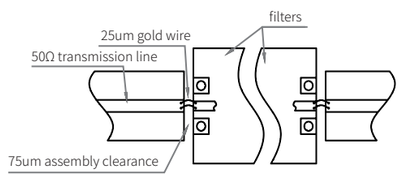
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	9.0	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB4700-2700-11

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

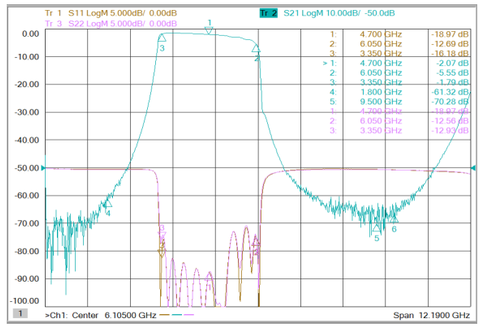
Environmental Parameters

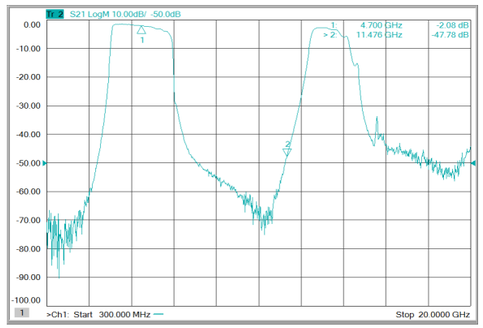
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	4.7	-	GHz
Band Freq	3.35	-	6.05	GHz
Fc IL	-	2.2	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@1.8 GHz			
	⩾60dB@9.5 GHz			

Typical Curve





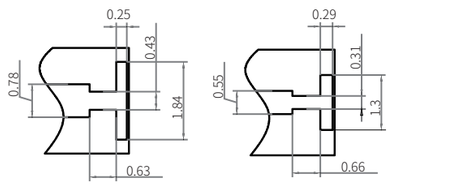
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

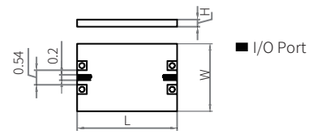


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

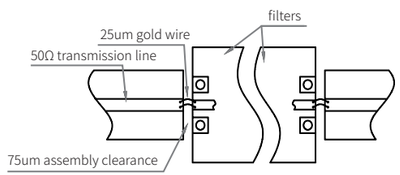
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7	mm
W	6.8	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB5100-200-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

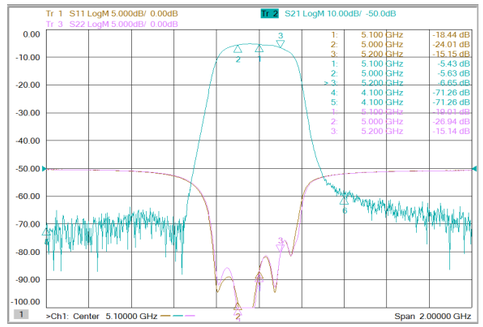
Environmental Parameters

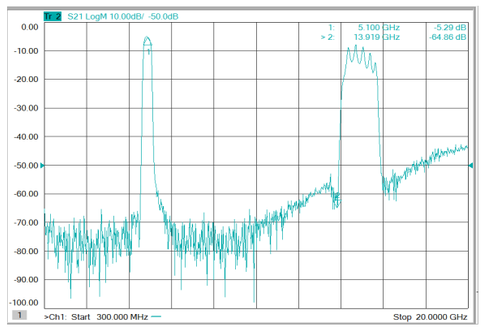
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	5.1	-	GHz
Band Freq	5.0	-	5.2	GHz
Fc IL	-	5.5	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@4.6GHz			
	⩾50dB@5.7 GHz			

Typical Curve





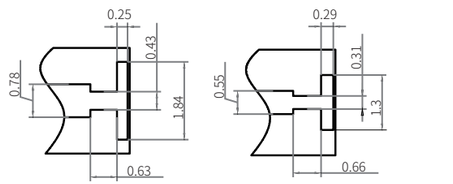
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

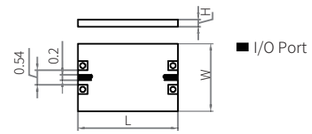


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

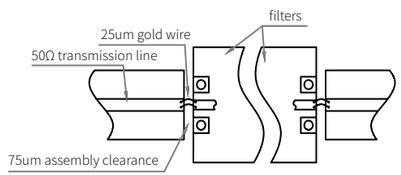
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	6	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB5195.5-209-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

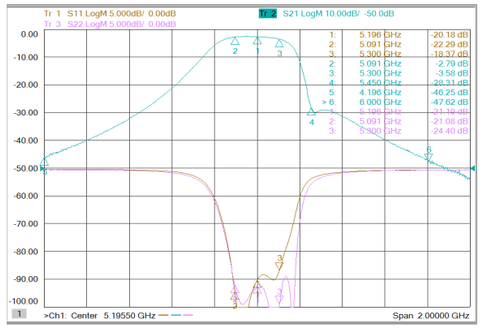
Environmental Parameters

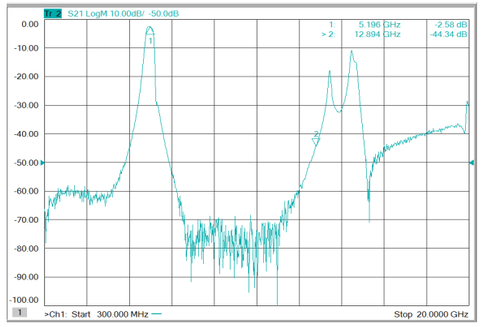
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

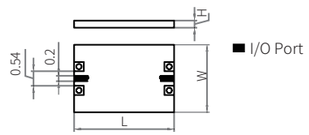
	Min	Typical	Max	
Center Freq	-	5.1955	-	GHz
Band Freq	5.091	-	5.3	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾30dB@4.13 GHz			
	⩾20dB@5.45 GHz			

Typical Curve





Overall Dimensions



notation	value	unit
L	8	mm
W	5	mm
H	0.254	mm

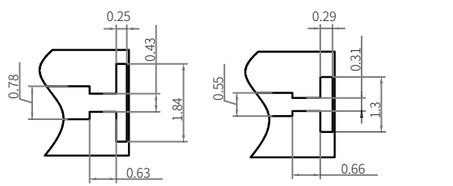
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

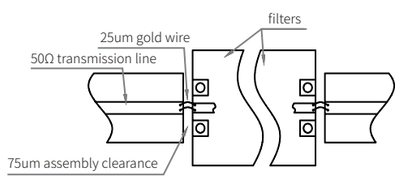


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Suggested Assembly Drawings



IYFTB5575-250-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

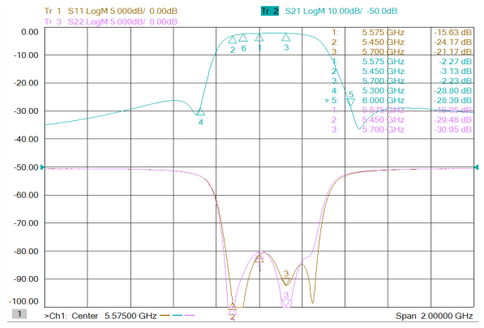
Environmental Parameters

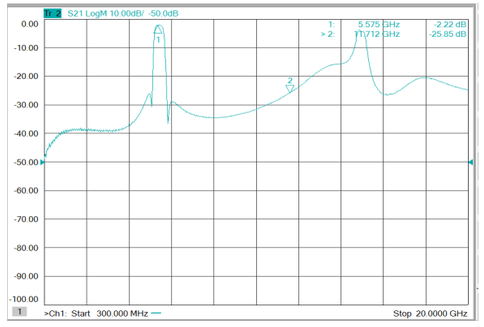
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

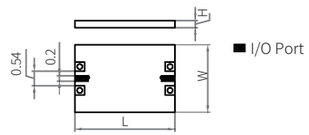
	Min	Typical	Max	
Center Freq	-	5.575	-	GHz
Band Freq	5.45	-	5.7	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾25dB@5.3 GHz			
	⩾25dB@6.0 GHz			

Typical Curve





Overall Dimensions



notation	value	unit
L	8	mm
W	5	mm
H	0.254	mm

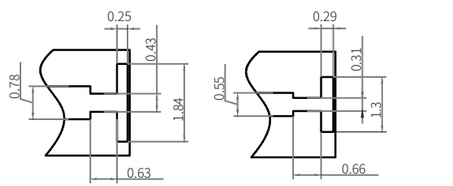
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

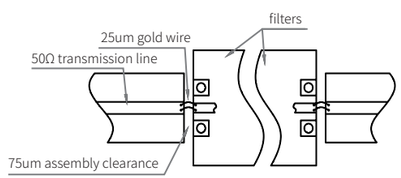


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Suggested Assembly Drawings



IYFTB5750-750-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

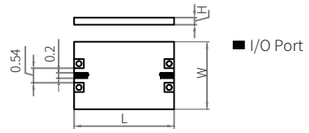
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

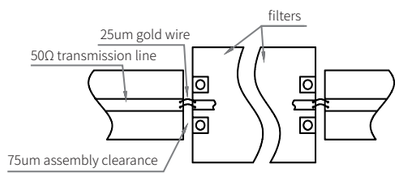
	Min	Typical	Max	
Center Freq	-	5.75	-	GHz
Band Freq	5.25	-	6.0	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@4.0 GHz			
	⩾60dB@7.0 GHz			

Overall Dimensions

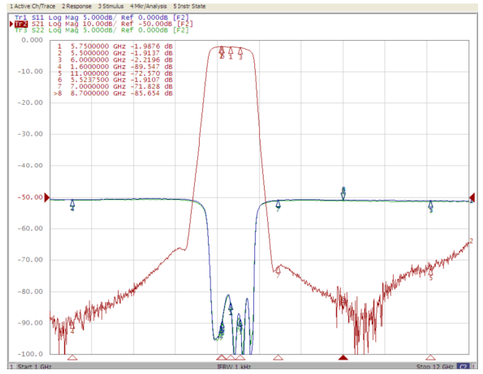


notation	value	unit
L	8.5	mm
W	5.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



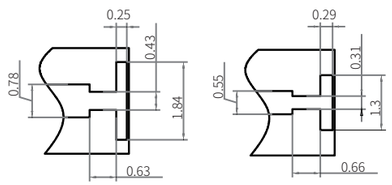
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB6000-4000-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

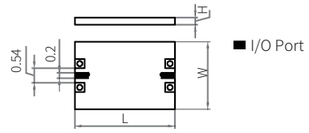
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

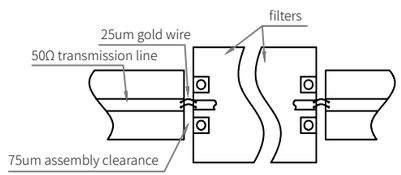
	Min	Typical	Max	
Center Freq	-	6	-	GHz
Band Freq	4	-	8	GHz
Fc IL	-	1.5	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@3 GHz			
	⩾45dB@9 GHz			

Overall Dimensions

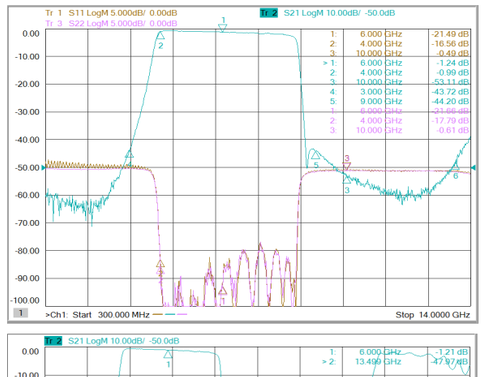


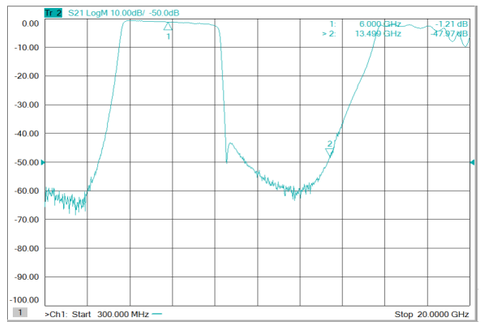
notation	value	unit
L	7.5	mm
W	6	mm
H	0.381	mm

Suggested Assembly Drawings



Typical Curve





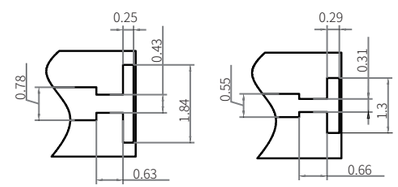
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB6050-300-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

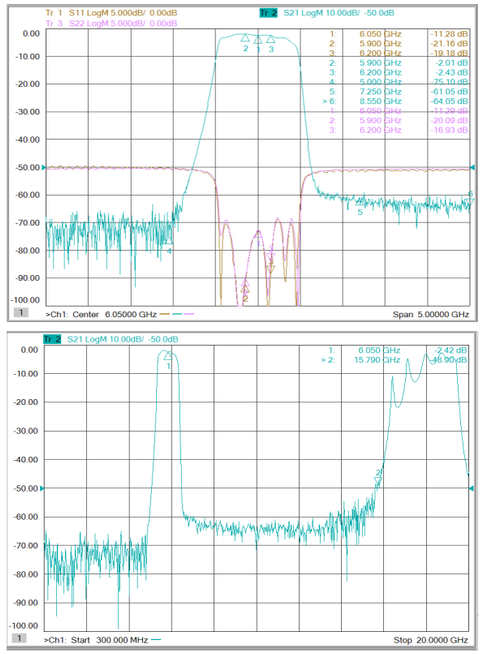
Environmental Parameters

Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	6.05	-	GHz
Band Freq	5.9	-	6.2	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@5 GHz			
	⩾60dB@7.25 GHz			

Typical Curve



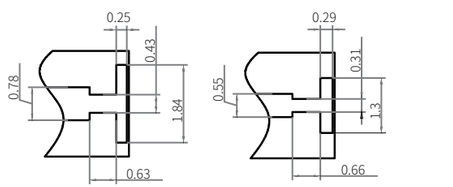
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

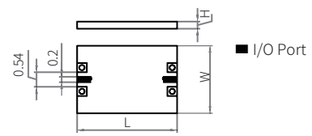


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

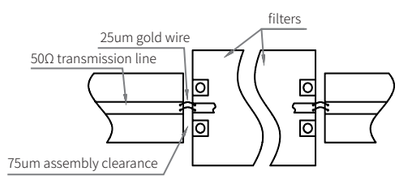
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	8.5	mm
W	5.5	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB6150-300-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

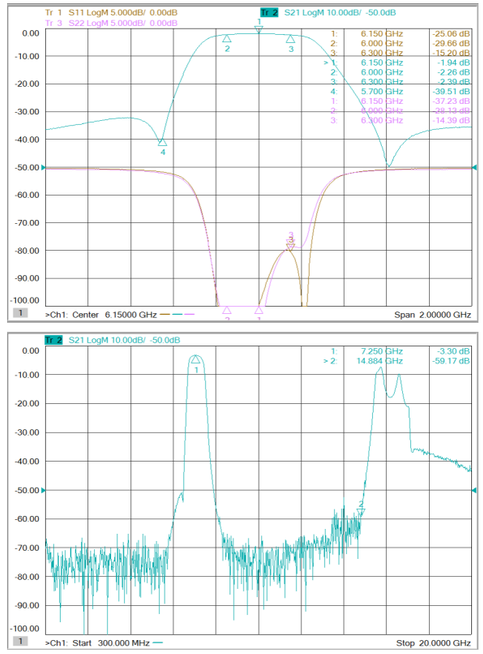
Environmental Parameters

Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	6.15	-	GHz
Band Freq	6.0	-	6.3	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@3 GHz			
	⩾40dB@9 GHz			

Typical Curve



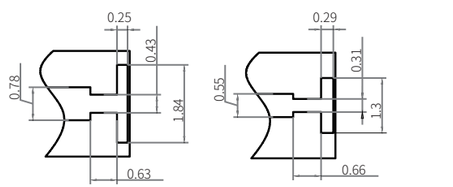
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

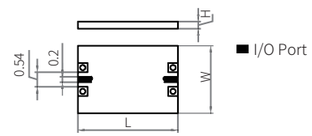


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

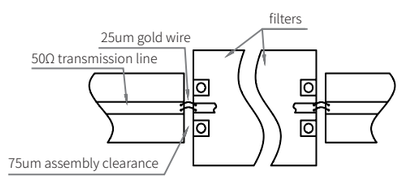
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	8	mm
W	5	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB6820-1100-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

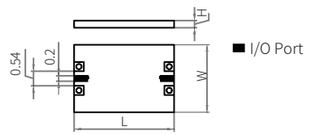
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

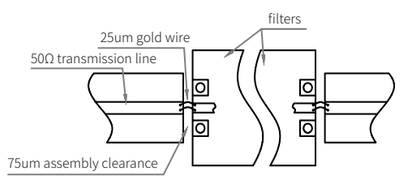
	Min	Typical	Max	
Center Freq	-	6.82	-	GHz
Band Freq	6.26	-	7.36	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	0.6	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@5.31 GHz			
	⩾45dB@8.59 GHz			

Overall Dimensions

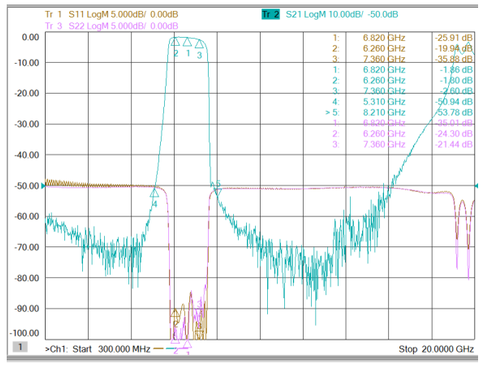


notation	value	unit
L	8.5	mm
W	5.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



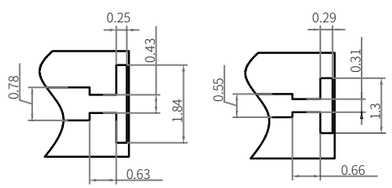
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB7170-1020-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

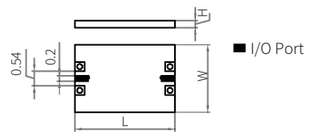
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

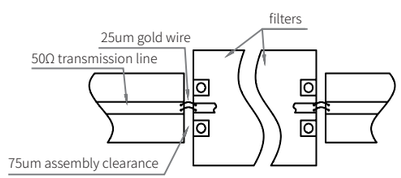
	Min	Typical	Max	
Center Freq	-	7.17	-	GHz
Band Freq	6.66	-	7.68	GHz
Fc IL	-	3	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾30dB@6.36GHz			
	⩾40dB@8.64GHz			

Overall Dimensions

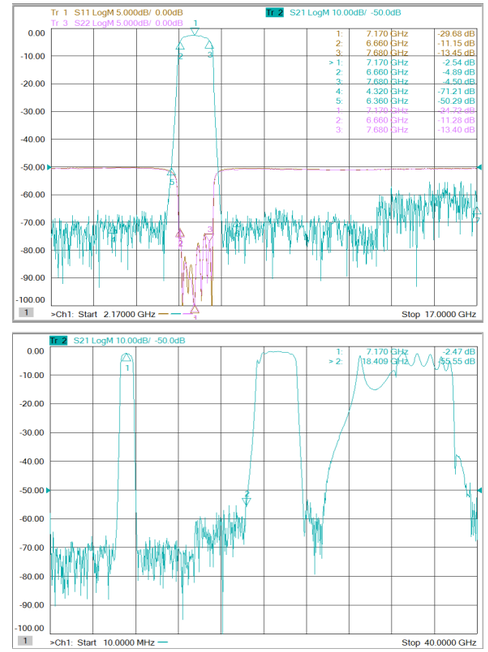


notation	value	unit
L	8.5	mm
W	5.0	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



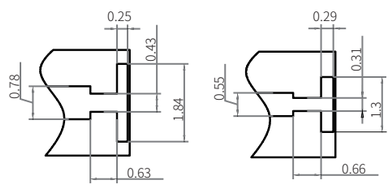
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB7250-500-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

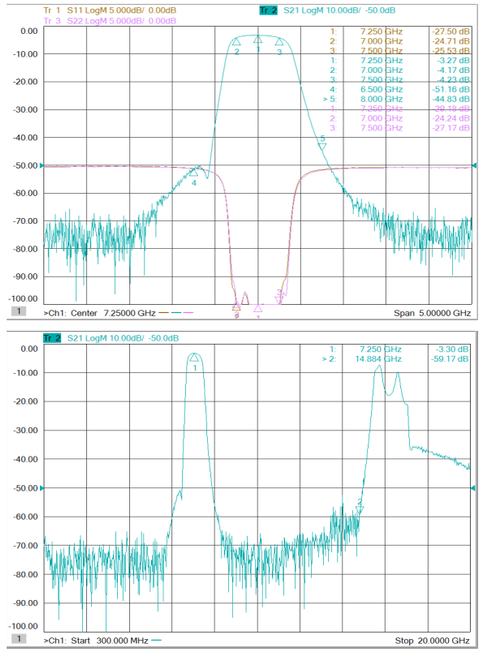
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

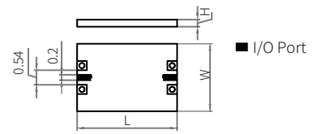
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	7.25	-	GHz
Band Freq	7	-	7.5	GHz
Fc IL	-	4.5	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@6.5 GHz ⩾40dB@8 GHz			

Typical Curve

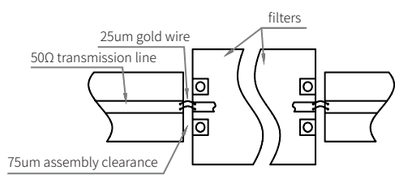


Overall Dimensions



notation	value	unit
L	10	mm
W	4	mm
H	0.254	mm

Suggested Assembly Drawings



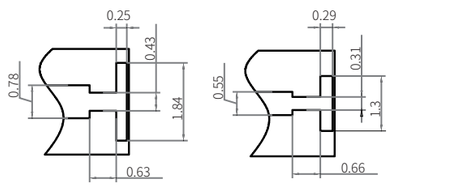
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB7250-2500-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

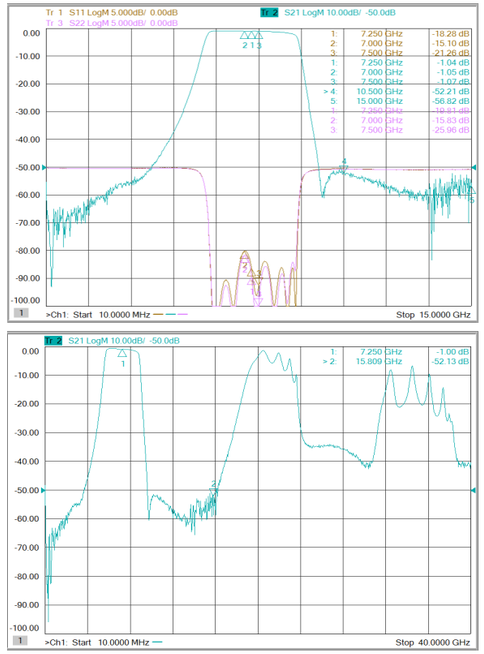
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

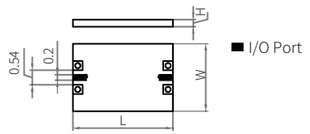
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	7.25	-	GHz
Band Freq	6	-	8.5	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@4.0 GHz ⩾40dB@10.5 GHz			

Typical Curve

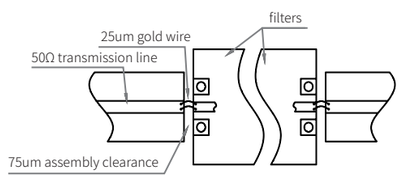


Overall Dimensions



notation	value	unit
L	5.5	mm
W	5.0	mm
H	0.254	mm

Suggested Assembly Drawings



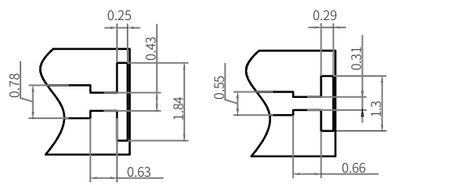
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB7800-800-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

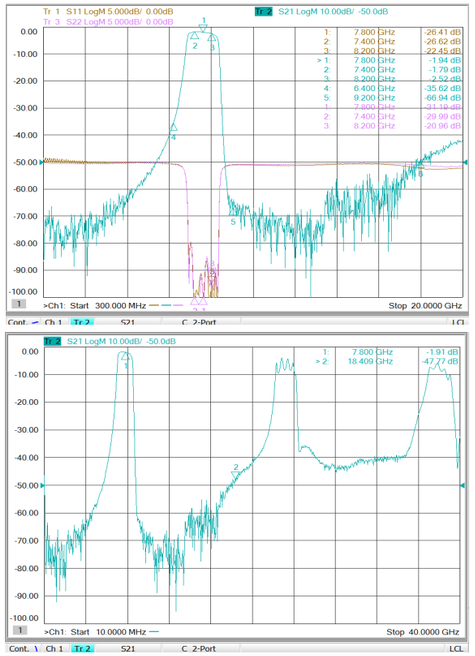
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	7.8	-	GHz
Band Freq	7.4	-	8.2	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@6.4 GHz			
	⩾45dB@9.2 GHz			

Typical Curve



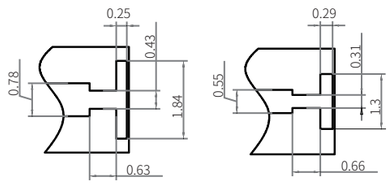
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

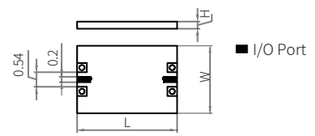


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

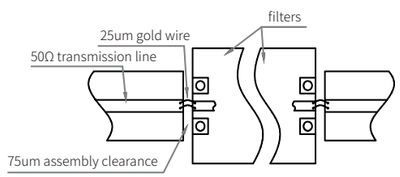
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	8.5	mm
W	5	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB8000-4000-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

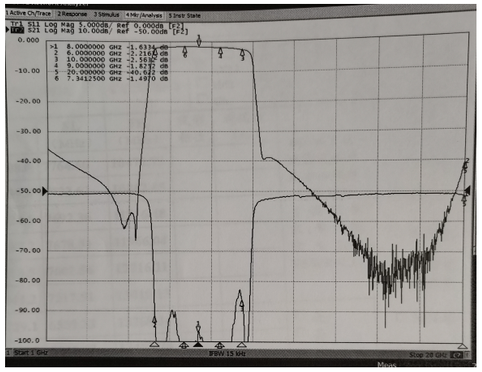
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	8.0	-	GHz
Band Freq	6	-	10	GHz
Fc IL	-	1.8	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@5.15 GHz			
	⩾40dB@11.6 GHz			

Typical Curve



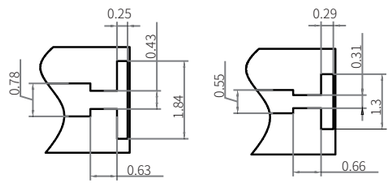
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

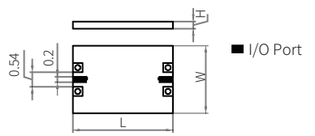


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

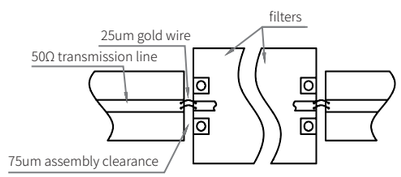
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	8.0	mm
W	4.8	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB8000-4000-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

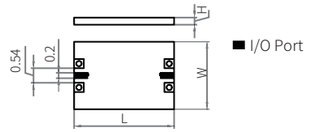
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

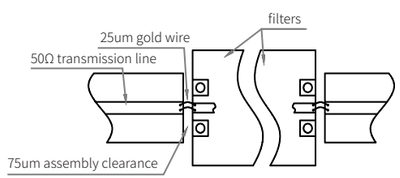
	Min	Typical	Max	
Center Freq	-	8	-	GHz
Band Freq	6	-	10	GHz
Fc IL	-	1.5	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	
Rejection	⩾40dB@4 GHz			
	⩾40dB@11.5 GHz			

Overall Dimensions

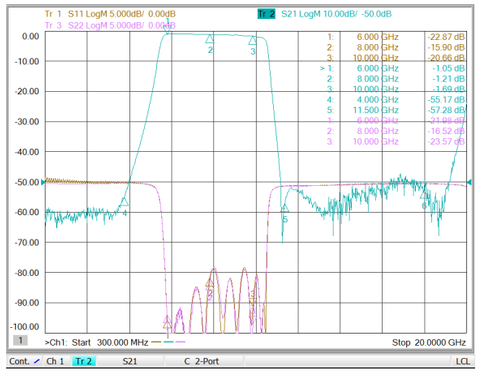


notation	value	unit
L	7	mm
W	4.9	mm
H	0.381	mm

Suggested Assembly Drawings



Typical Curve



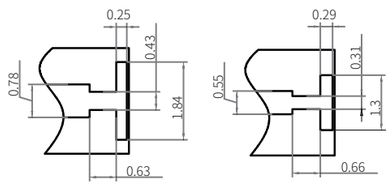
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB8000-4400-11

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

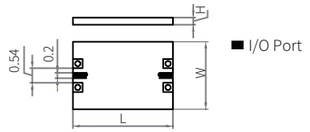
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

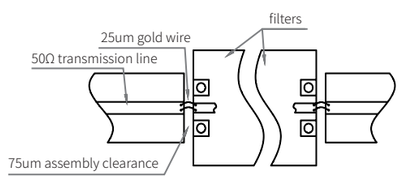
	Min	Typical	Max	
Center Freq	-	8	-	GHz
Band Freq	5.8	-	10.2	GHz
Fc IL	-	2	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@3.5 GHz			
	⩾60dB@15 GHz			

Overall Dimensions

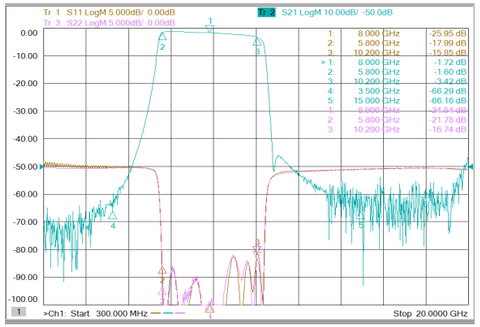


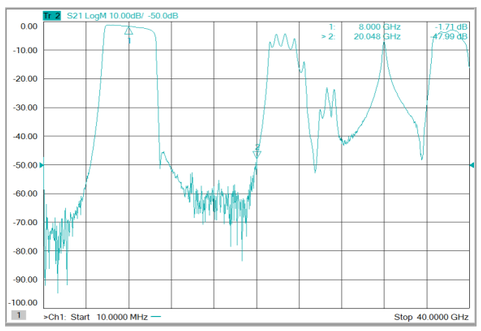
notation	value	unit
L	7	mm
W	4.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve





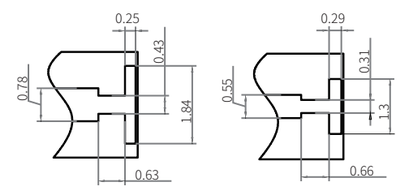
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB8170-1020-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

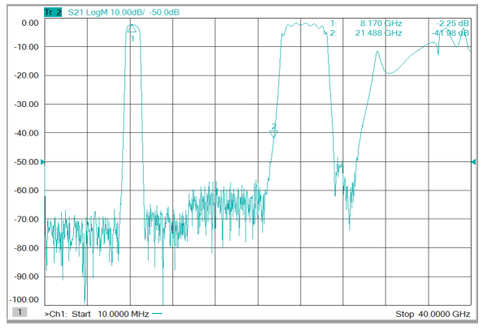
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

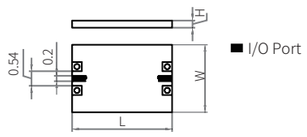
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	8.17	-	GHz
Band Freq	7.66	-	8.68	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾30dB@7.36 GHz			
	⩾40dB@10.64 GHz			

Typical Curve

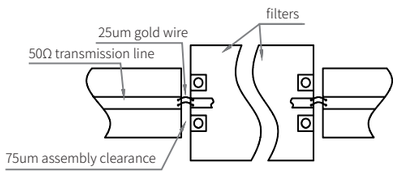


Overall Dimensions



notation	value	unit
L	8.5	mm
W	4.5	mm
H	0.254	mm

Suggested Assembly Drawings



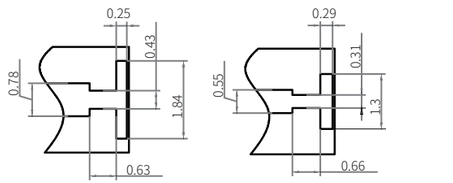
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB8250-500-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

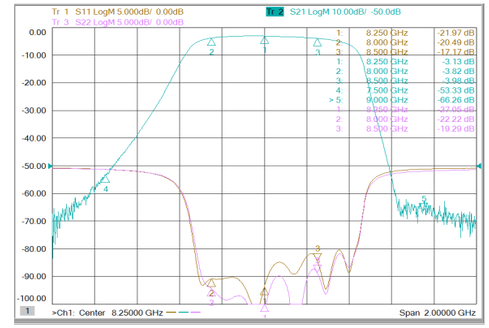
Environmental Parameters

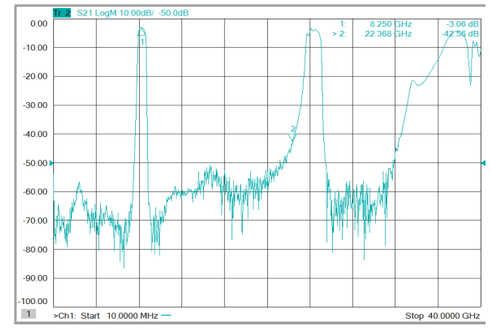
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

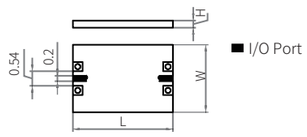
	Min	Typical	Max	
Center Freq	-	8.25	-	GHz
Band Freq	8	-	8.5	GHz
Fc IL	-	3.5	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@7.5 GHz			
	⩾40dB@9.0 GHz			

Typical Curve



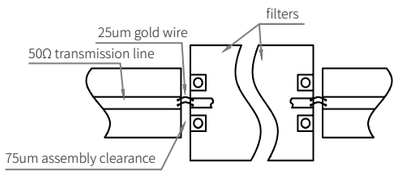


Overall Dimensions



notation	value	unit
L	10.0	mm
W	4.0	mm
H	0.254	mm

Suggested Assembly Drawings



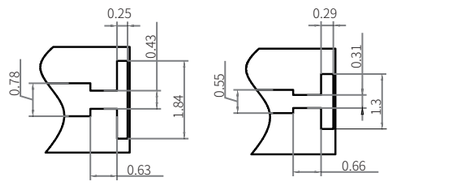
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB8750-2100-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

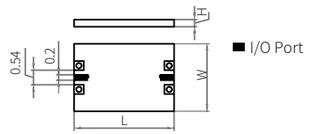
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

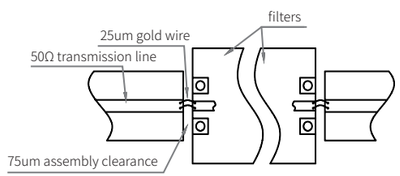
	Min	Typical	Max	
Center Freq	-	8.75	-	GHz
Band Freq	7.7	-	9.8	GHz
Fc IL	-	1.8	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@6.2 GHz			
	⩾45dB@11.25 GHz			

Overall Dimensions

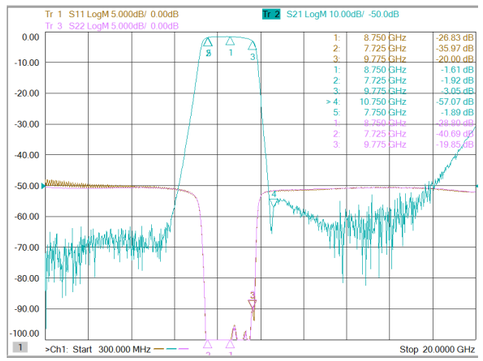


notation	value	unit
L	5.5	mm
W	4.2	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



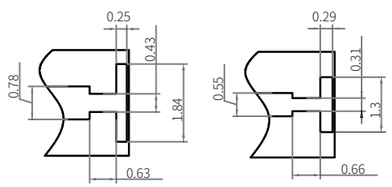
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB9170A-1020-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

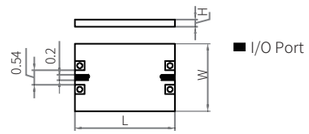
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

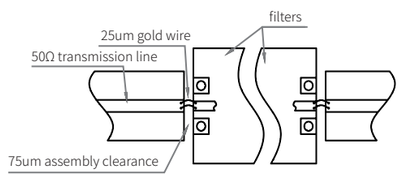
	Min	Typical	Max	
Center Freq	-	9.17	-	GHz
Band Freq	8.66	-	9.68	GHz
Fc IL	-	3	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@7.8 GHz			
	⩾40dB@10.55 GHz			

Overall Dimensions

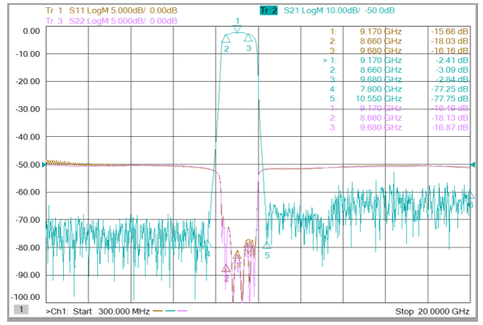


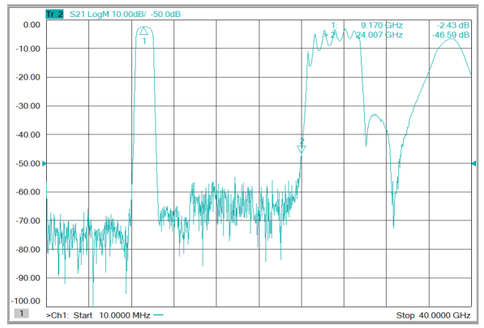
notation	value	unit
L	9	mm
W	4	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve





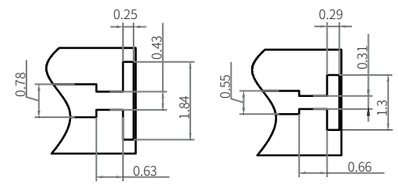
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB9185-2370-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

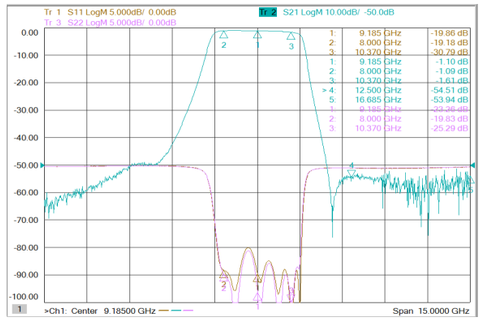
Environmental Parameters

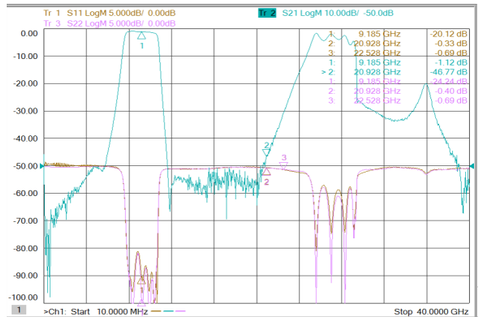
Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

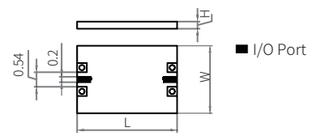
	Min	Typical	Max	
Center Freq	-	9.185	-	GHz
Band Freq	8	-	10.37	GHz
Fc IL	-	1.5	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@6.2 GHz			
	⩾40dB@12.2 GHz			

Typical Curve



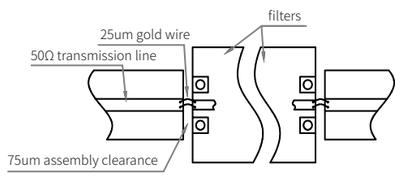


Overall Dimensions



notation	value	unit
L	5.5	mm
W	4.0	mm
H	0.254	mm

Suggested Assembly Drawings



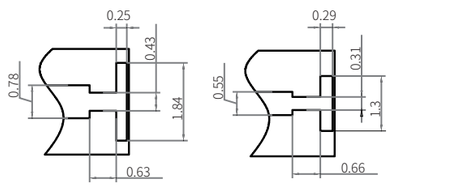
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / ℃) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB9200-200-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

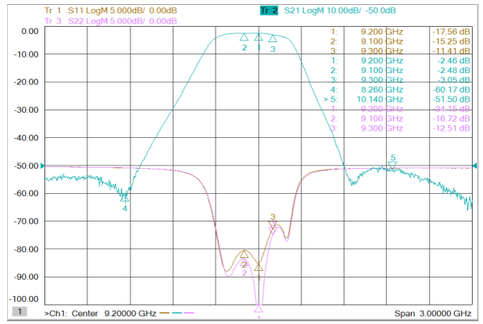
Environmental Parameters

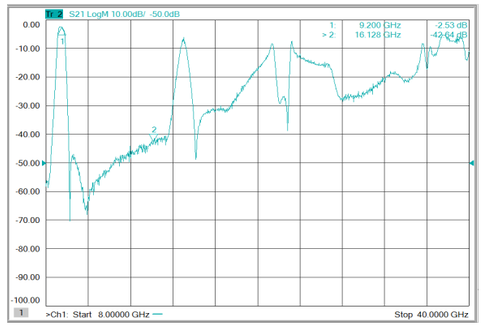
Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

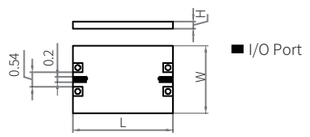
	Min	Typical	Max	
Center Freq	-	9.2	-	GHz
Band Freq	9.1	-	9.3	GHz
Fc IL	-	3.0	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@8.26 GHz			
	⩾50dB@10.14 GHz			

Typical Curve



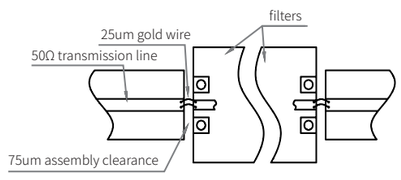


Overall Dimensions



notation	value	unit
L	7.5	mm
W	5.3	mm
H	0.381	mm

Suggested Assembly Drawings



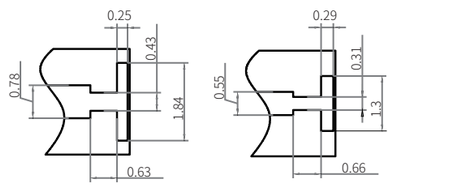
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / ℃) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB9497.5-1835-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

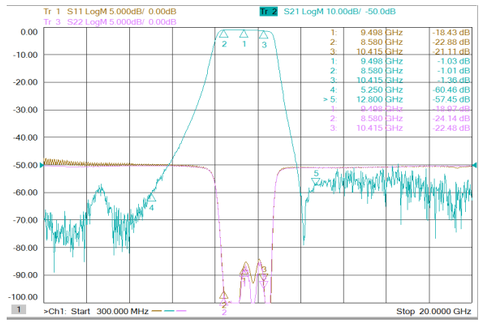
Environmental Parameters

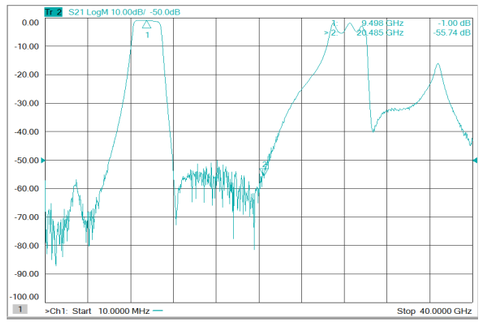
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	9.4975	-	GHz
Band Freq	8.58	-	10.415	GHz
Fc IL	-	1.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@5.25 GHz			
	⩾50dB@12.8 GHz			

Typical Curve





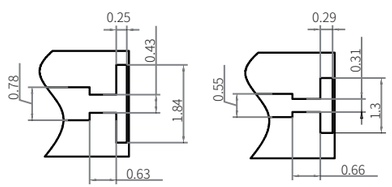
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

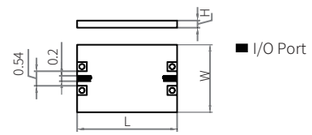


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

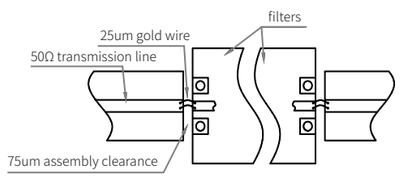
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	5.5	mm
W	3.8	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB9500-3500-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

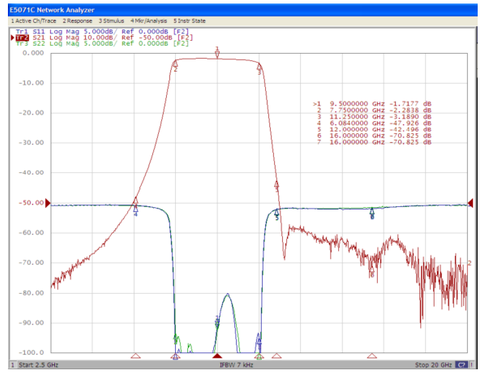
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	9.5	-	GHz
Band Freq	7.75	-	11.25	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@DC~6 GHz			
	⩾45dB@12.5~20 GHz			

Typical Curve



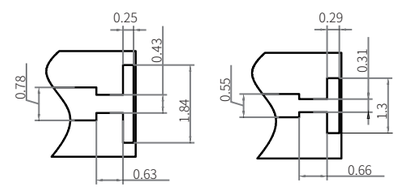
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

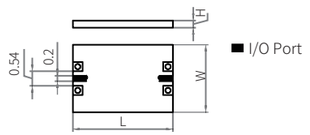


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

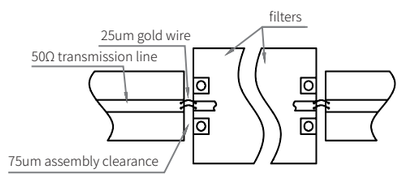
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.0	mm
W	4.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB9500-1000-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

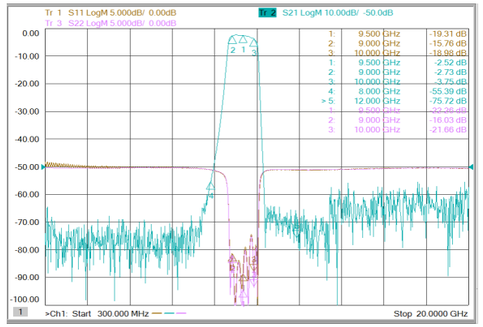
Environmental Parameters

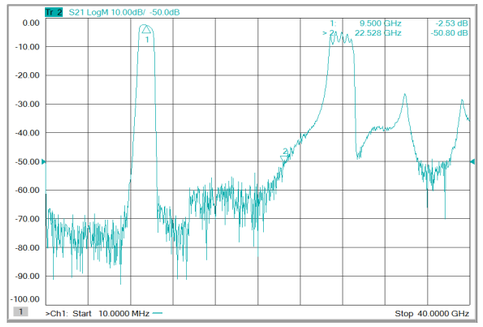
Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

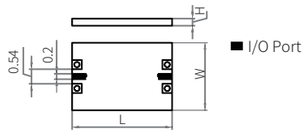
	Min	Typical	Max	
Center Freq	-	9.5	-	GHz
Band Freq	9.0	-	10	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	-
Rejection	⩾30dB@8 GHz			
	⩾60dB@12 GHz			

Typical Curve



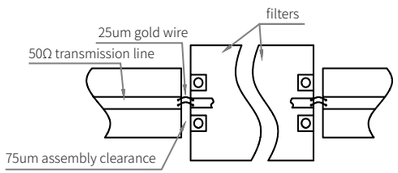


Overall Dimensions



notation	value	unit
L	9.0	mm
W	4.0	mm
H	0.254	mm

Suggested Assembly Drawings



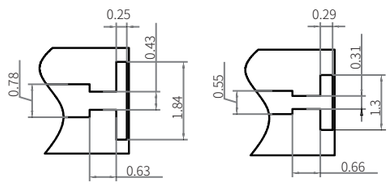
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / ℃) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB9500-1800-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

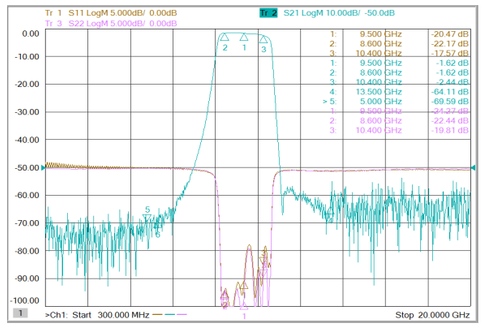
Environmental Parameters

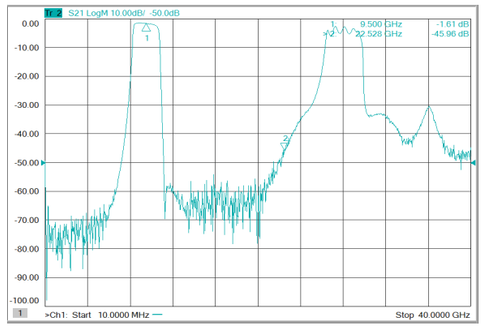
Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

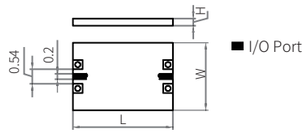
	Min	Typical	Max	
Center Freq	-	9.5	-	GHz
Band Freq	8.6	-	10.4	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@5 GHz			
	⩾60dB@12 GHz			

Typical Curve



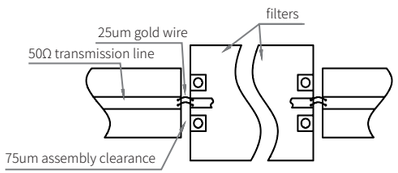


Overall Dimensions



notation	value	unit
L	7.5	mm
W	4.0	mm
H	0.254	mm

Suggested Assembly Drawings



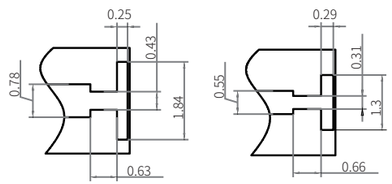
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / ℃) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB9650-3900-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

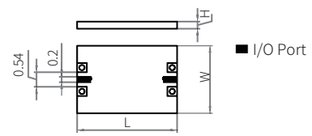
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

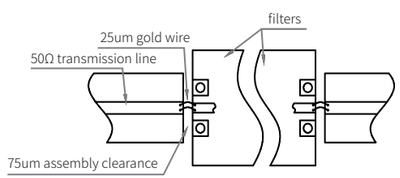
	Min	Typical	Max	
Center Freq	-	9.65	-	GHz
Band Freq	7.7	-	11.6	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@4 GHz			
	⩾50dB@16 GHz			

Overall Dimensions

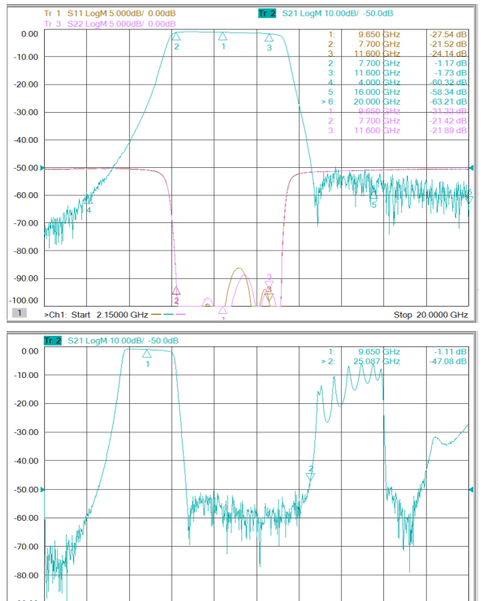


notation	value	unit
L	6.5	mm
W	3.7	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



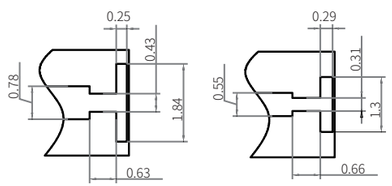
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB9750-100-5

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

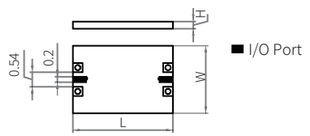
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

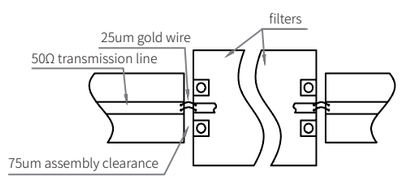
	Min	Typical	Max	
Center Freq	-	9.75	-	GHz
Band Freq	9.7	-	9.8	GHz
Fc IL	-	4.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@9 GHz			
	⩾40dB@10.5 GHz			

Overall Dimensions

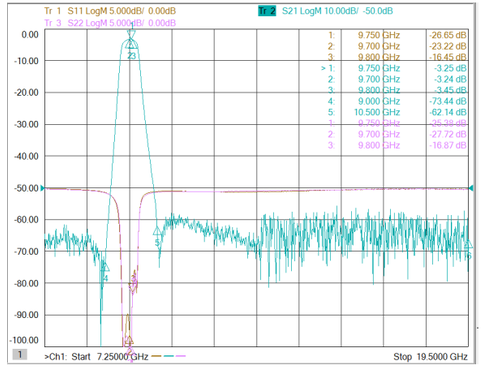


notation	value	unit
L	5.5	mm
W	4.0	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



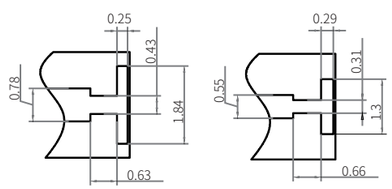
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB10000-2000-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

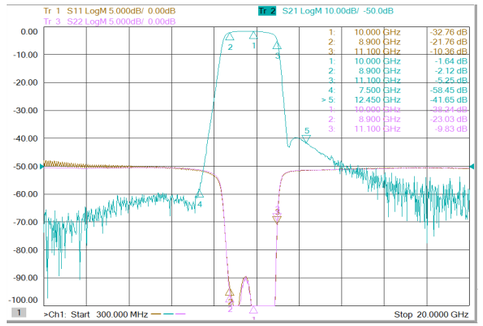
Environmental Parameters

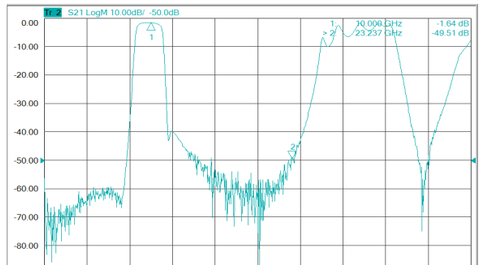
Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	10	-	GHz
Band Freq	9	-	11	GHz
Fc IL	-	2	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@7.5 GHz			
	⩾45dB@12.45 GHz			

Typical Curve





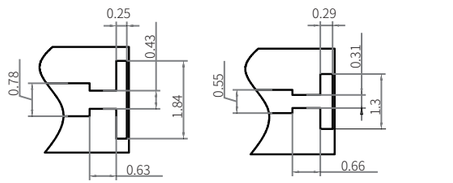
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / ℃) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

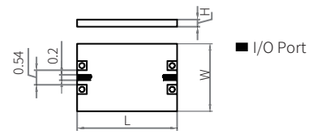


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

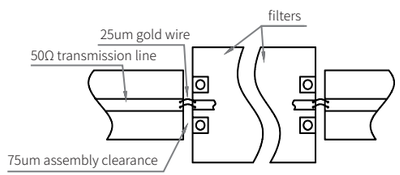
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	5.5	mm
W	3.8	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB10000-4500-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

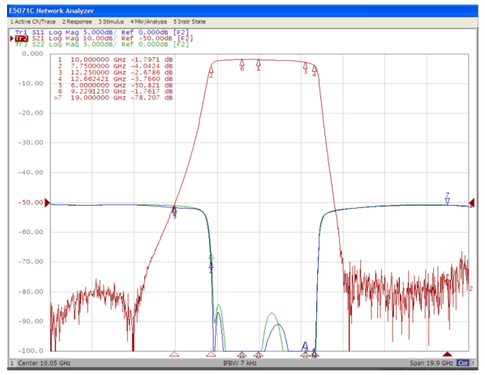
Environmental Parameters

Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	10	-	GHz
Band Freq	7.75	-	12.25	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@DC~6 GHz			
	⩾45dB@14~24 GHz			

Typical Curve



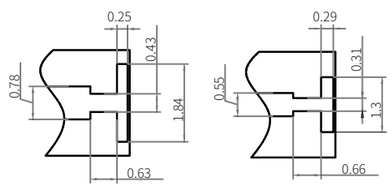
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / ℃) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

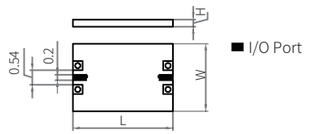


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

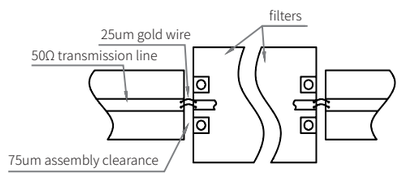
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	3.8	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB10000-6000-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

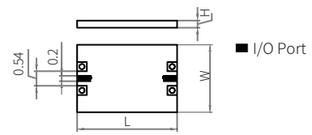
Environmental Parameters

Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

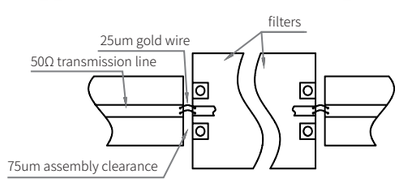
	Min	Typical	Max	
Center Freq	-	10	-	GHz
Band Freq	7	-	13	GHz
Fc IL	-	1.5	-	dB
Passband Ripple	-	-	0.8	dB
VSWR	-	1.8	-	-
Rejection	⩾30dB@5GHz			
	⩾35dB@16 GHz			

Overall Dimensions

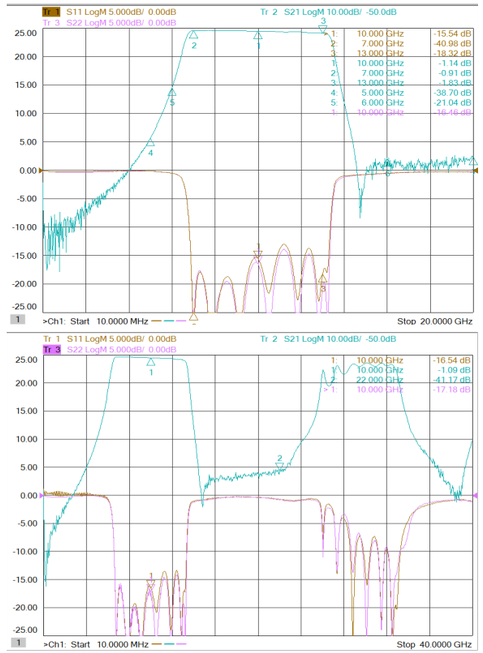


notation	value	unit
L	7.5	mm
W	3.5	mm
H	0.381	mm

Suggested Assembly Drawings



Typical Curve



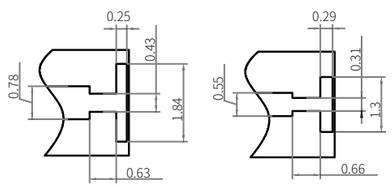
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / ℃) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB10150-4900-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

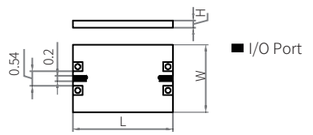
Environmental Parameters

Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

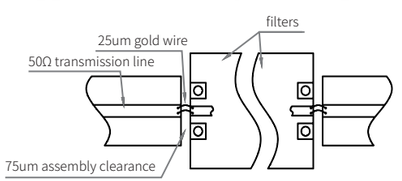
	Min	Typical	Max	
Center Freq	-	10.15	-	GHz
Band Freq	7.7		12.6	GHz
Fc IL	-	1.8	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@4.8 GHz			
	⩾45dB@15.6 GHz			

Overall Dimensions

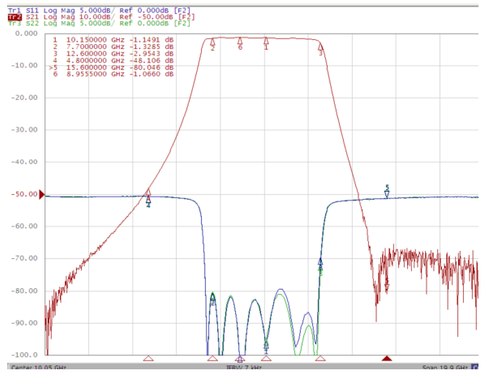


notation	value	unit
L	7.0	mm
W	4.0	mm
H	0.381	mm

Suggested Assembly Drawings



Typical Curve



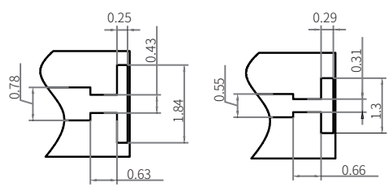
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / ℃) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB10170-1020-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

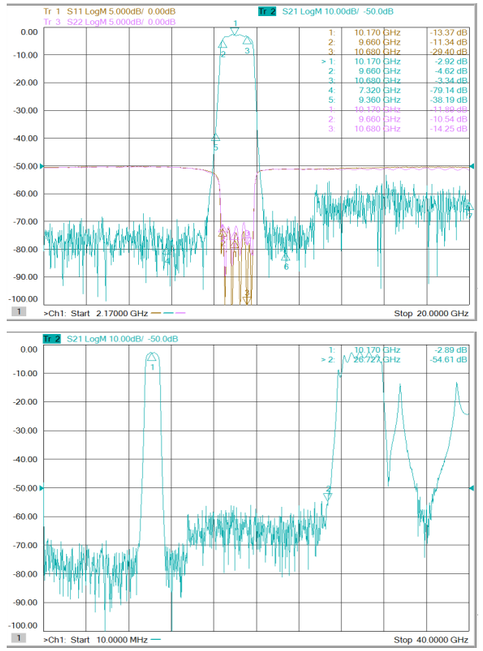
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

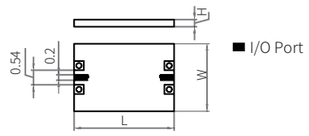
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	10.17	-	GHz
Band Freq	9.66	-	10.68	GHz
Fc IL	-	3.0	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾30dB@9.36 GHz			
	⩾40dB@12.3 GHz			

Typical Curve

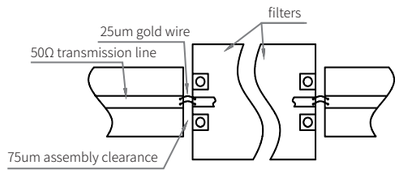


Overall Dimensions



notation	value	unit
L	9.5	mm
W	4.0	mm
H	0.254	mm

Suggested Assembly Drawings



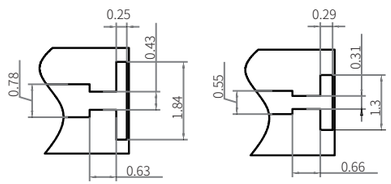
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB10170A-1020-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

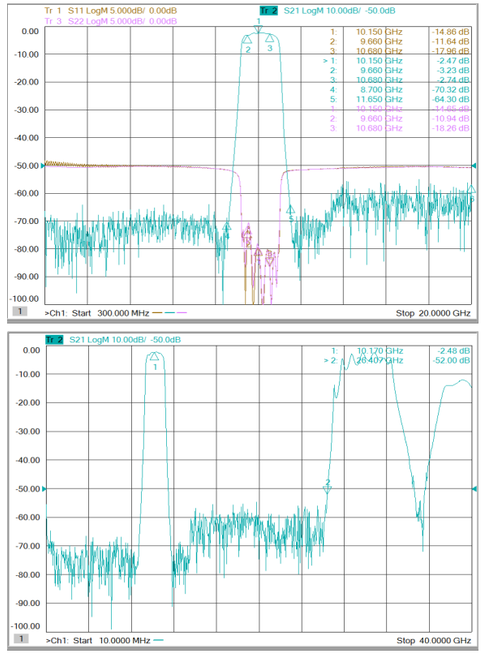
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

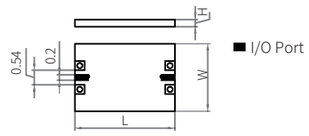
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	10.17	-	GHz
Band Freq	9.66	-	10.68	GHz
Fc IL	-	3	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@8.7 GHz			
	⩾40dB@11.65 GHz			

Typical Curve

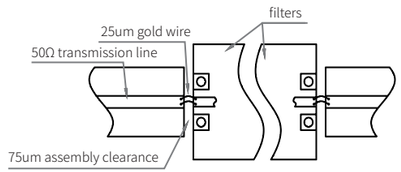


Overall Dimensions



notation	value	unit
L	9.5	mm
W	4	mm
H	0.254	mm

Suggested Assembly Drawings



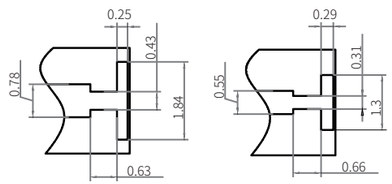
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB10200-1920-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

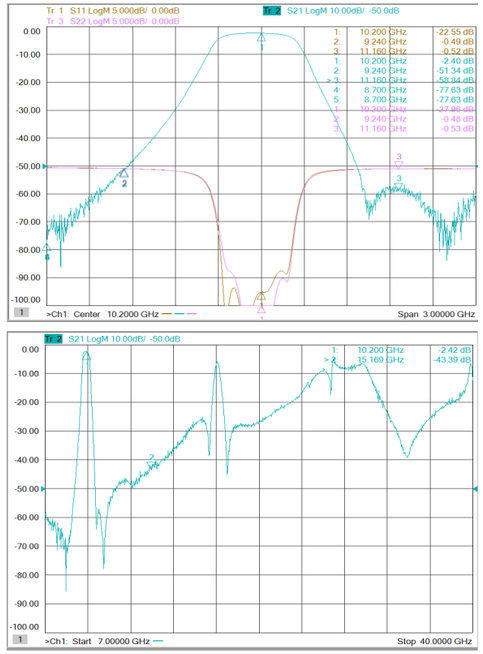
Environmental Parameters

Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	10.2	-	GHz
Band Freq	-	-	-	GHz
Fc IL	-	3	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@9.24 GHz			
	⩾50dB@11.16 GHz			

Typical Curve



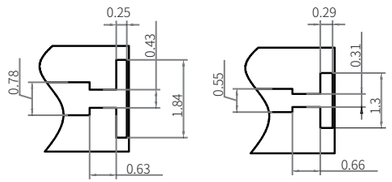
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

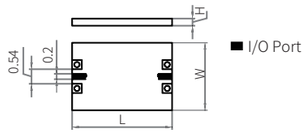


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

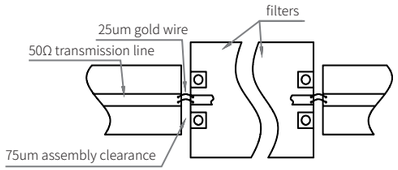
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	5	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB10200-5000-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

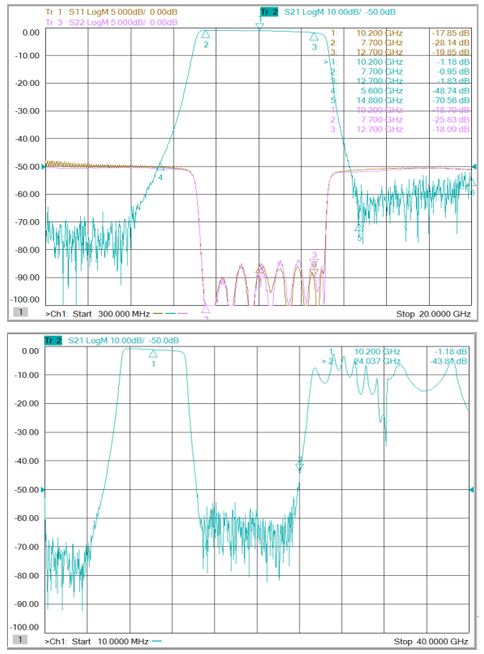
Environmental Parameters

Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	10.2	-	GHz
Band Freq	7.7	-	12.7	GHz
Fc IL	-	1.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@5.6 GHz			
	⩾40dB@14.8 GHz			

Typical Curve



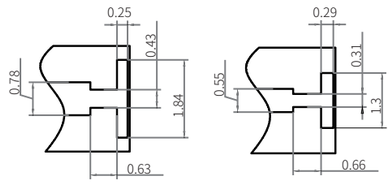
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

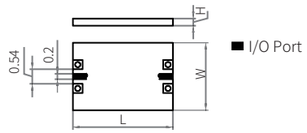


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

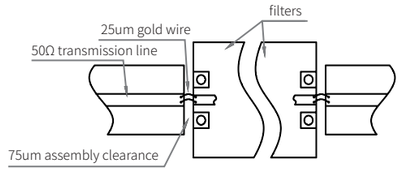
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7	mm
W	4	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB10920-1920-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

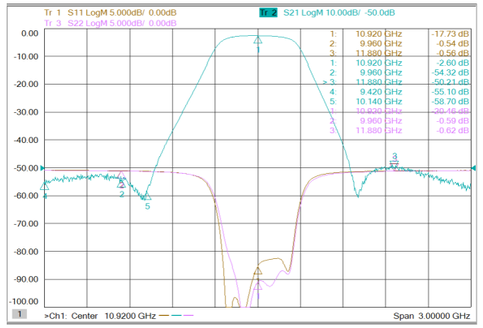
Environmental Parameters

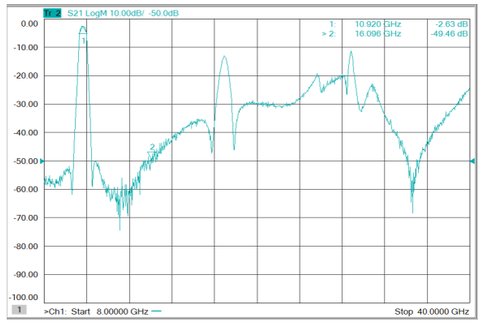
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	10.92	-	GHz
Band Freq	-	-	-	GHz
Fc IL	-	3.0	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@9.94 GHz			
	⩾40dB@11.88 GHz			

Typical Curve





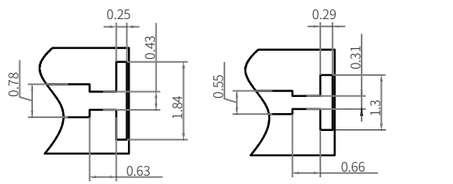
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

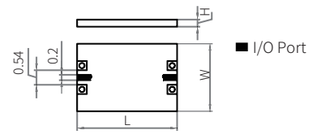


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

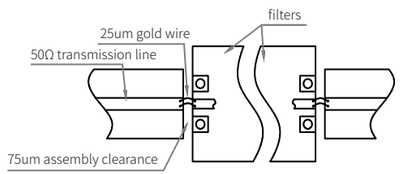
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	5	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB11000-2500-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

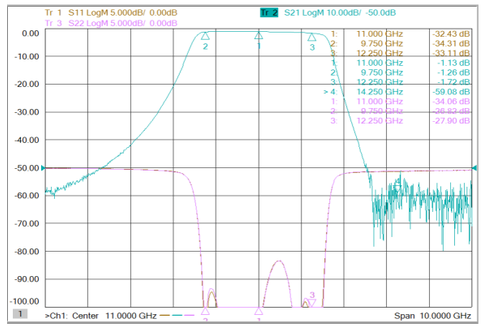
Environmental Parameters

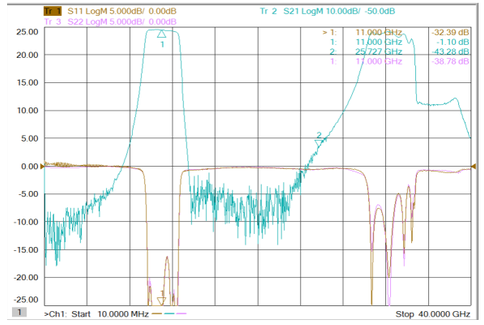
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	11	-	GHz
Band Freq	9.75	-	12.25	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@7.8 GHz			
	⩾40dB@14.2 GHz			

Typical Curve





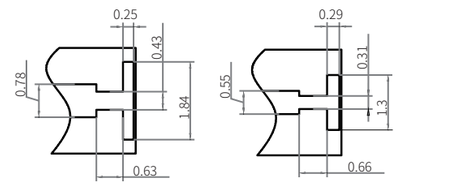
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

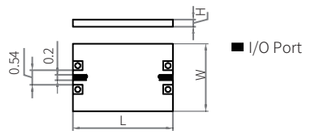


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

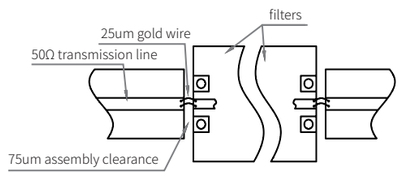
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	6.0	mm
W	3.5	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB11000-6200-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

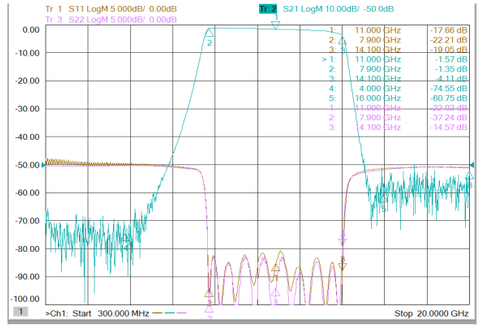
Environmental Parameters

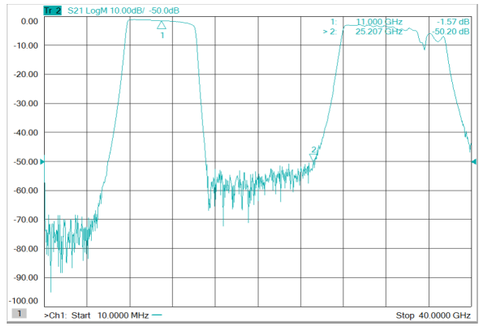
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	11	-	GHz
Band Freq	7.9	-	14.1	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@4 GHz			
	⩾40dB@16 GHz			

Typical Curve





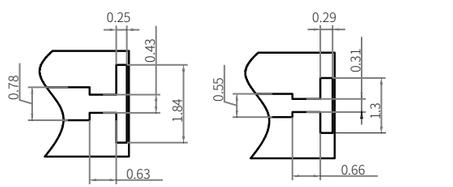
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

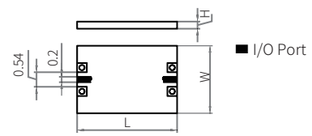


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

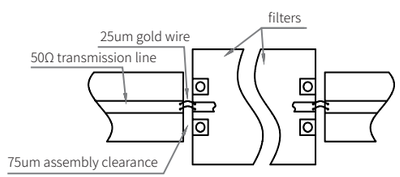
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	9.0	mm
W	4.0	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB11200-600-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

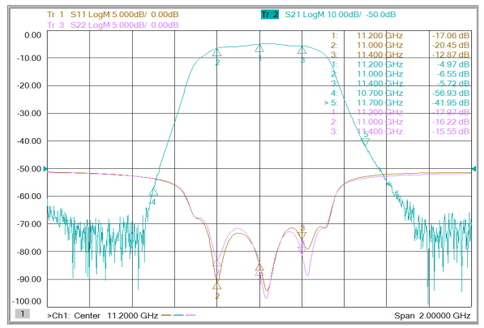
Environmental Parameters

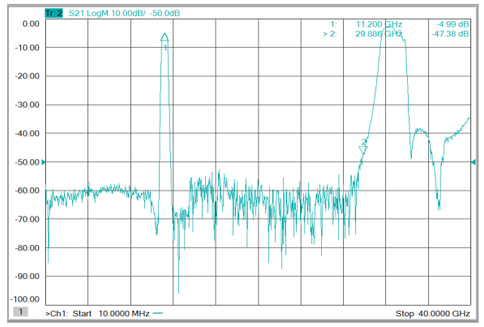
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	11.2	-	GHz
Band Freq	10.9	-	11.5	GHz
Fc IL	-	5.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@9.6 GHz			
	⩾50dB@12.1 GHz			

Typical Curve





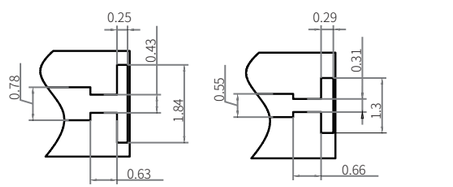
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

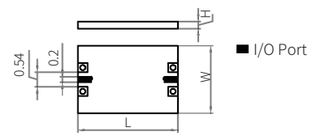


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

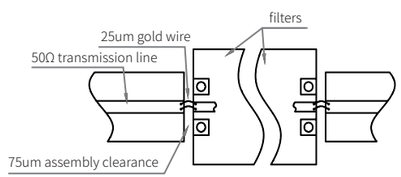
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	3.5	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB11300-1800-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

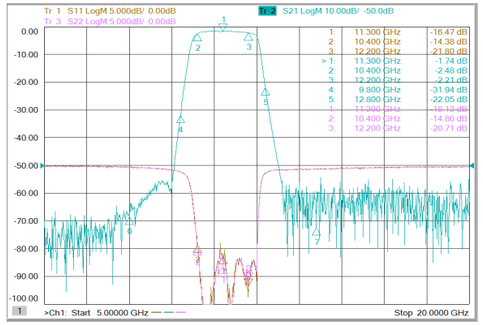
Environmental Parameters

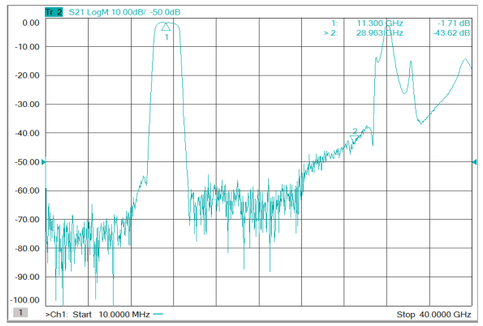
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	11.3	-	GHz
Band Freq	10.4	-	12.2	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.7	dB
VSWR	-	1.8	-	-
Rejection	⩾20dB@9.8GHz			
	⩾20dB@12.8 GHz			

Typical Curve





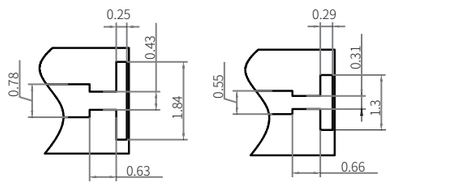
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

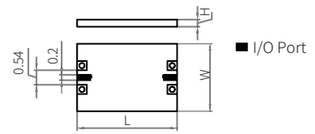


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

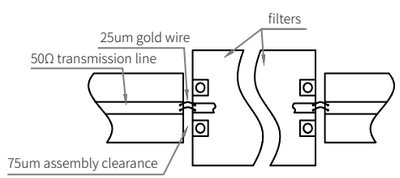
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	3	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB11400-2400-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

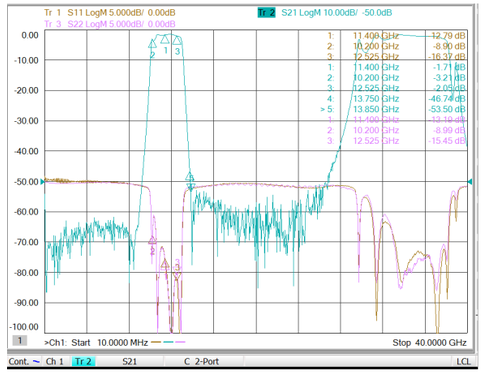
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	11.4	-	GHz
Band Freq	10.2	-	12.6	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@8.8 GHz			
	⩾40dB@13.85 GHz			

Typical Curve



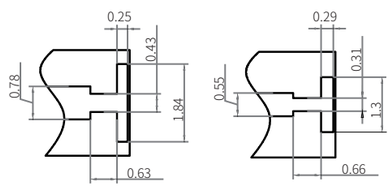
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

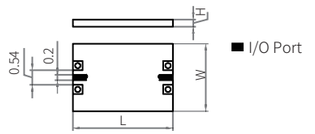


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

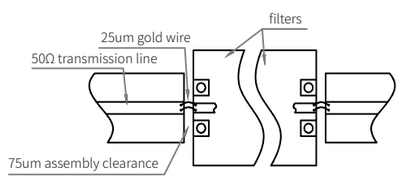
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	5.5	mm
W	3.5	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB11600-100-5

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

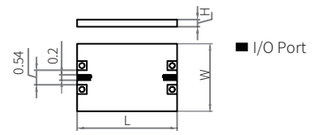
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

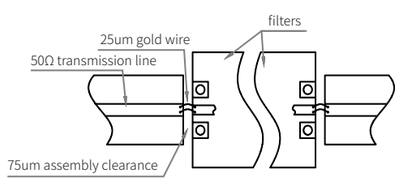
	Min	Typical	Max	
Center Freq	-	11.6	-	GHz
Band Freq	11.55	-	11.6	GHz
Fc IL	-	5.5	5	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	1.0	-
Rejection	⩾35dB@11 GHz			
	⩾35dB@12.1 GHz			

Overall Dimensions

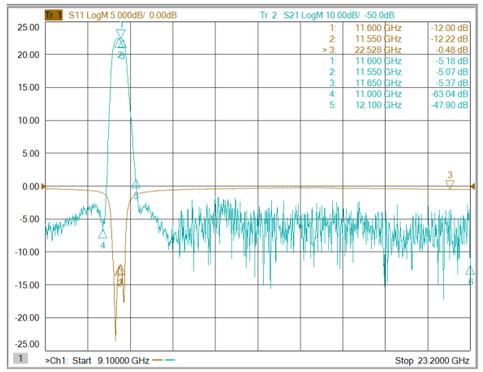


notation	value	unit
L	5.5	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



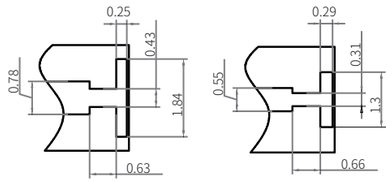
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB11860-200-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

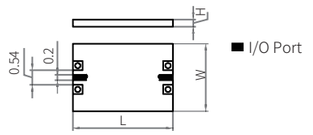
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

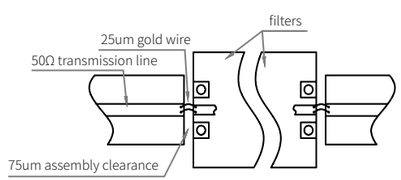
	Min	Typical	Max	
Center Freq	-	11.86	-	GHz
Band Freq	11.76	-	11.96	GHz
Fc IL	-	3.0	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@10.92 GHz			
	⩾50dB@12.8 GHz			

Overall Dimensions

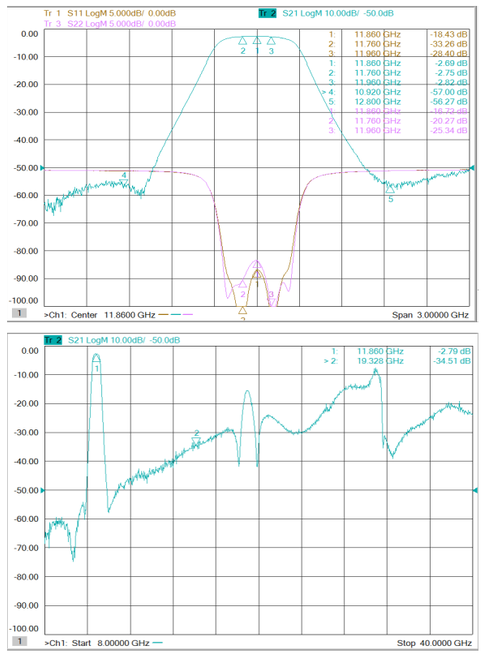


notation	value	unit
L	7.5	mm
W	5	mm
H	0.381	mm

Suggested Assembly Drawings



Typical Curve



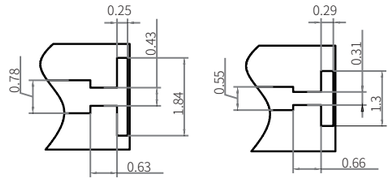
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB12000-3000-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

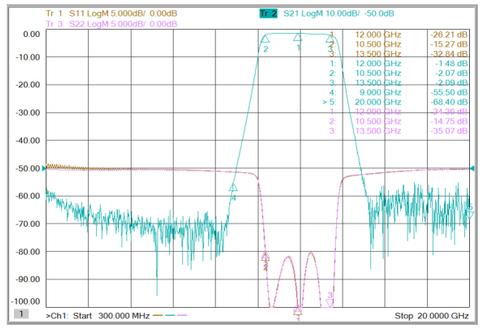
Environmental Parameters

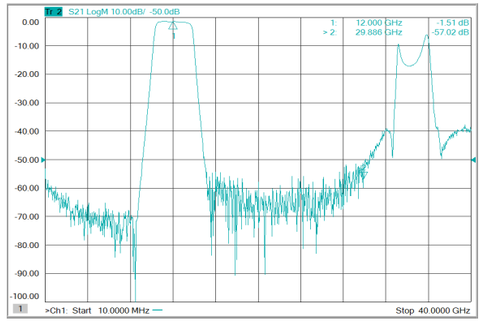
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	12	-	GHz
Band Freq	10.5	-	13.5	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.5	-	-
Rejection	⩾35dB@9 GHz			
	⩾40dB@15 GHz			

Typical Curve





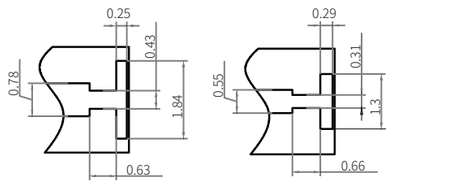
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

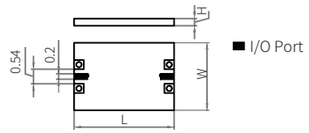


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

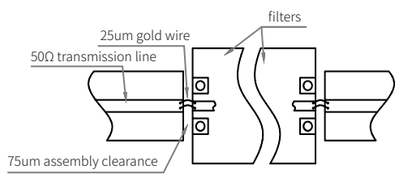
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	8	mm
W	3.2	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB12000-4400-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

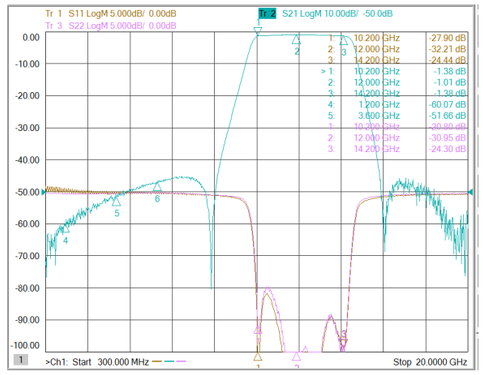
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	12	-	GHz
Band Freq	9.8	-	14.2	GHz
Fc IL	-	1.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@5 GHz			
	⩾60dB@20 GHz			

Typical Curve



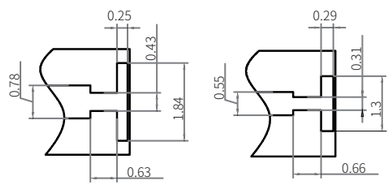
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

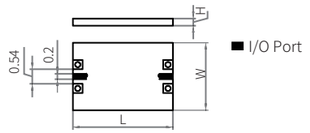


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

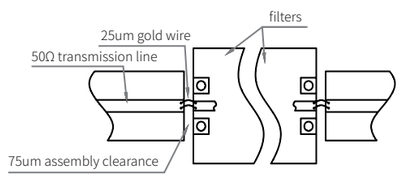
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB12500-2200-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

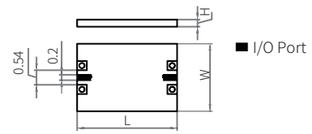
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

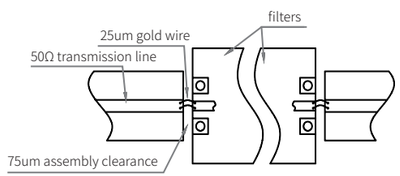
	Min	Typical	Max	
Center Freq	-	12.5	-	GHz
Band Freq	11.3	-	13.5	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾35dB@DC~10 GHz			
	⩾40dB@15~26.5 GHz			

Overall Dimensions

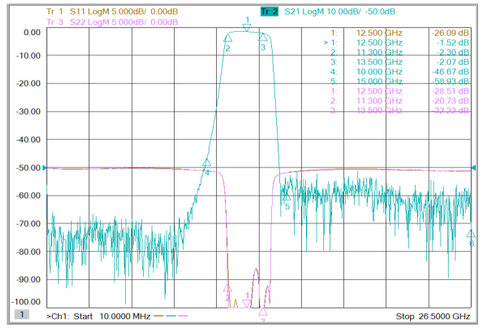


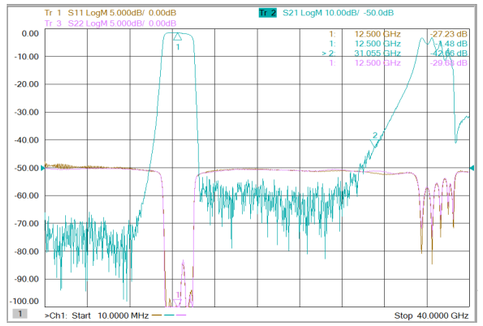
notation	value	unit
L	8.0	mm
W	3.2	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve





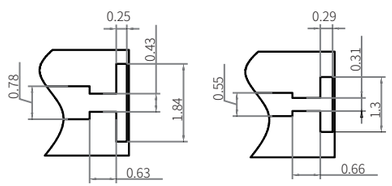
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB12500-3500-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

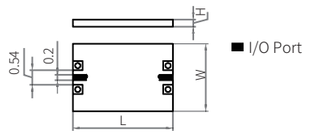
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

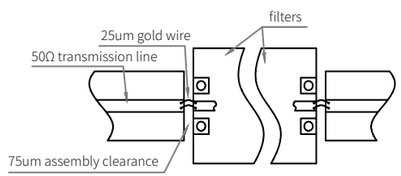
	Min	Typical	Max	
Center Freq	-	12.5	-	GHz
Band Freq	10.75		14.25	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.3	dB
VSWR	-	1.8		-
Rejection	⩾47dB@9.458 GHz			
	⩾46dB@15.9 GHz			

Overall Dimensions

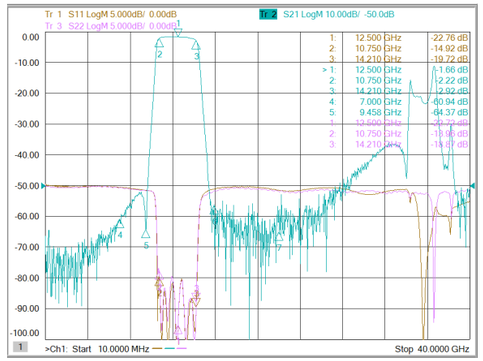


notation	value	unit
L	7	mm
W	3.4	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



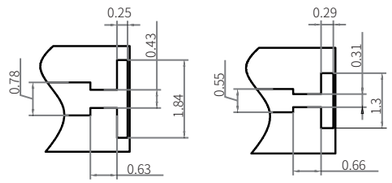
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB13000-1800-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

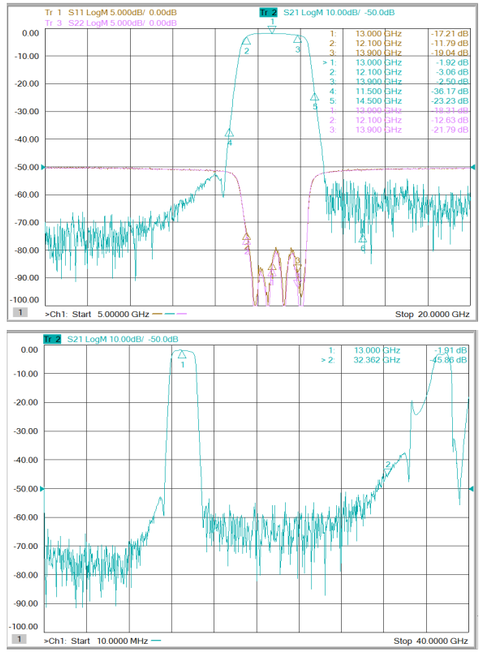
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	13	-	GHz
Band Freq	12.1	-	13.9	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.7	dB
VSWR	-	1.8	-	-
Rejection	⩾20dB@11.5GHz			
	⩾20dB@14.5GHz			

Typical Curve



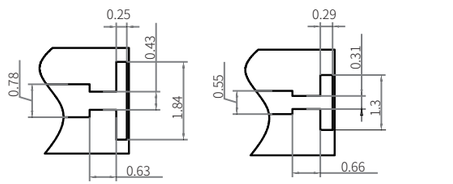
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

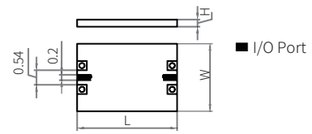


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

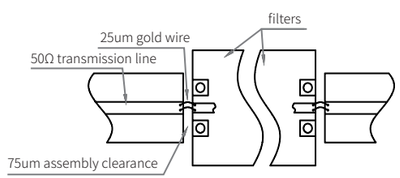
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	3	mm
H	0.381	mm

Suggested Assembly Drawings



IYFTB13000-2500-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

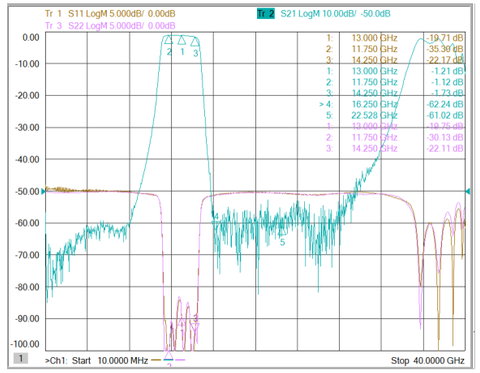
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	13	-	GHz
Band Freq	11.75		14.2	GHz
Fc IL	-	2.0	5	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	1.2	-
Rejection	⩾40dB@9.8 GHz			
	⩾40dB@16.2 GHz			

Typical Curve



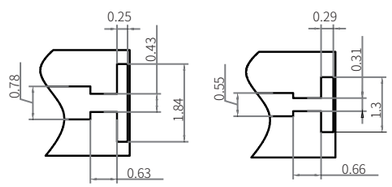
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

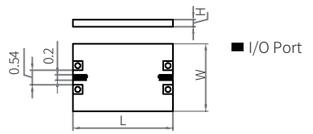


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

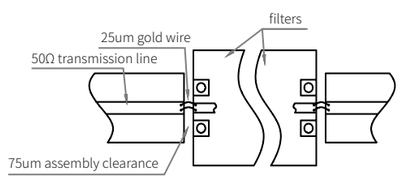
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	6.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB13000-4000-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

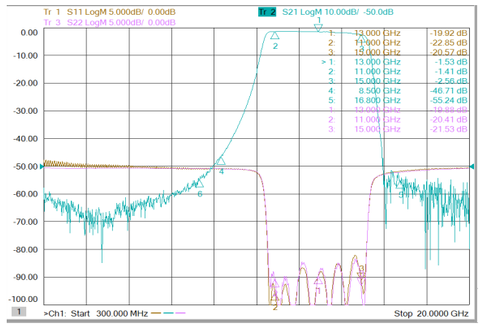
Environmental Parameters

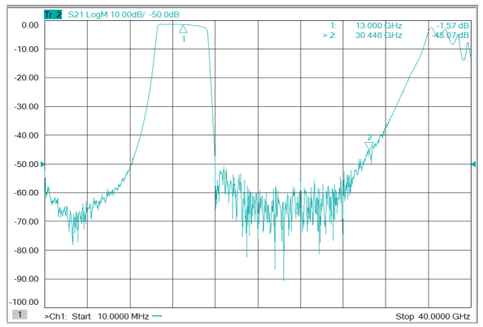
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	13	-	GHz
Band Freq	11	-	15	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@8.5 GHz			
	⩾50dB@16.8 GHz			

Typical Curve





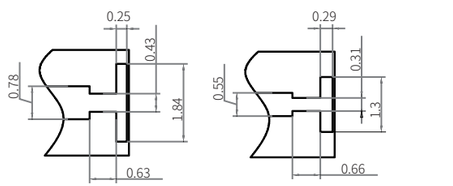
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

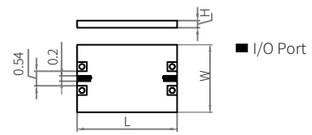


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

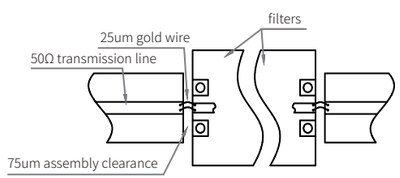
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	6.0	mm
W	3.2	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB13325-200-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

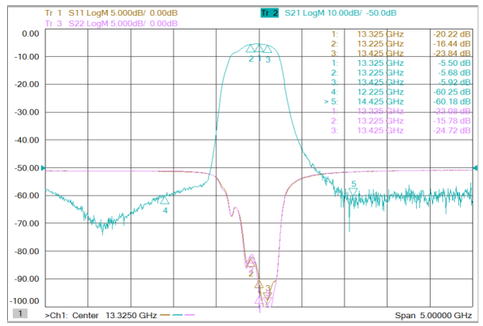
Environmental Parameters

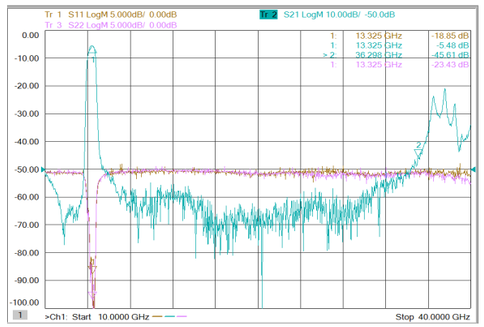
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	13.325	-	GHz
Band Freq	13.225	-	13.425	GHz
Fc IL	-	6.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@12.225 GHz			
	⩾50dB@14.425 GHz			

Typical Curve





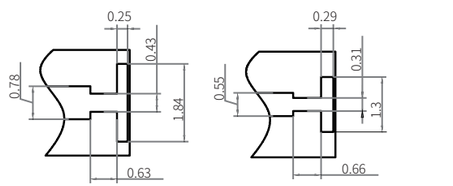
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

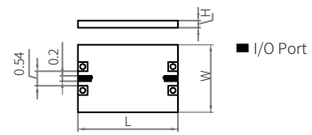


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

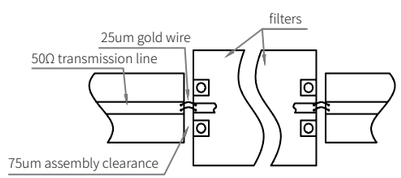
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	6.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB13000-600-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

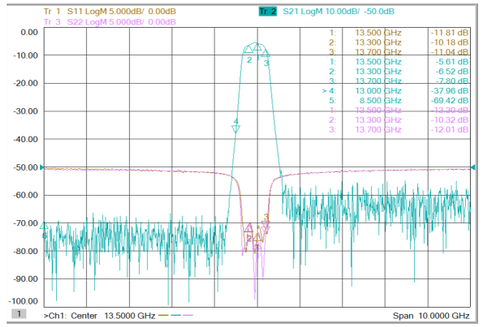
Environmental Parameters

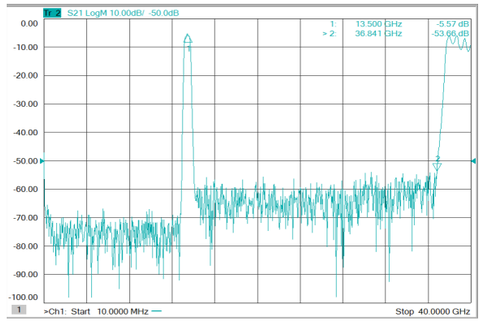
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	13	-	GHz
Band Freq	13.1	-	13.7	GHz
Fc IL	-	6.0	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾35dB@13 GHz			
	⩾35dB@14 GHz			

Typical Curve





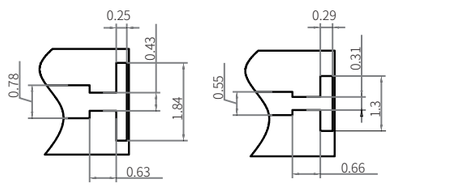
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

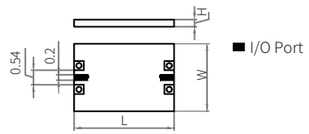


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

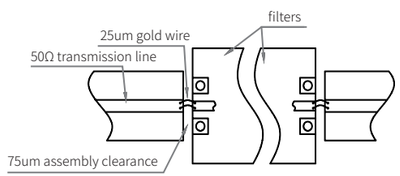
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB14250-3500-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

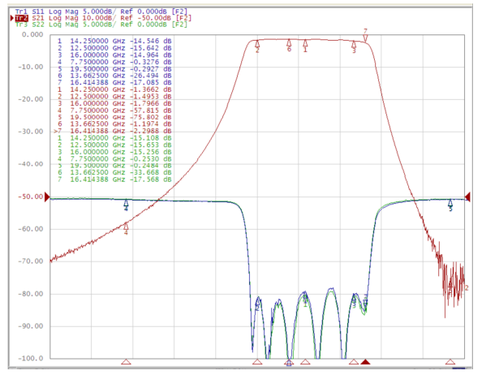
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	14.25	-	GHz
Band Freq	12.5	-	16	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@4.8 GHz			
	⩾45dB@15.6 GHz			

Typical Curve



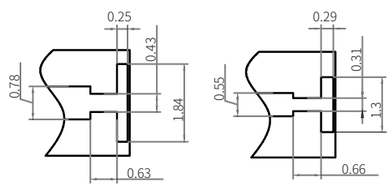
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

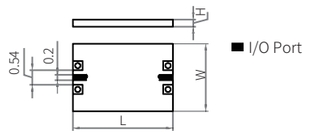


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

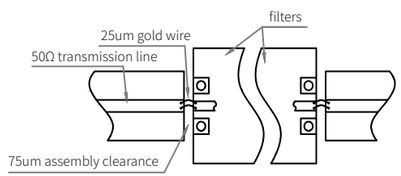
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.0	mm
W	2.9	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB14400-20-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

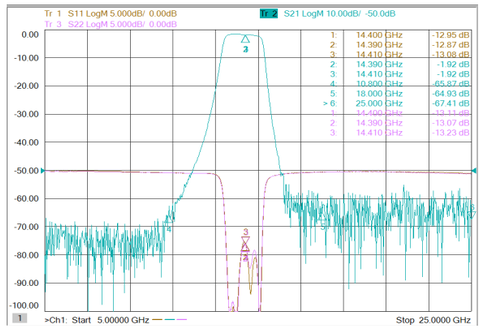
Environmental Parameters

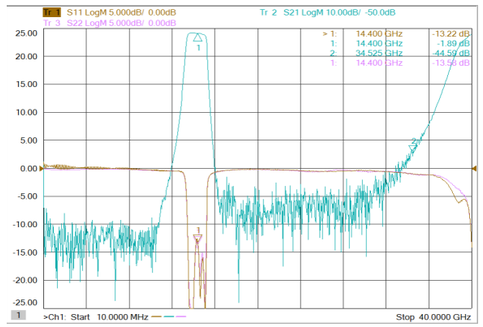
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	14.4	-	GHz
Band Freq	14.39	-	14.41	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@10.8 GHz			
	⩾40dB@18 GHz			

Typical Curve





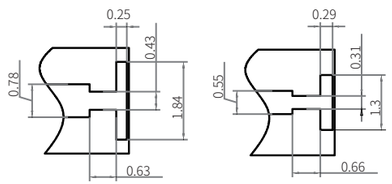
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

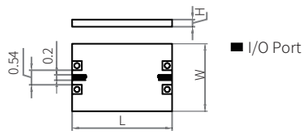


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

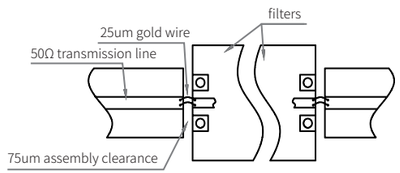
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB14450-900-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

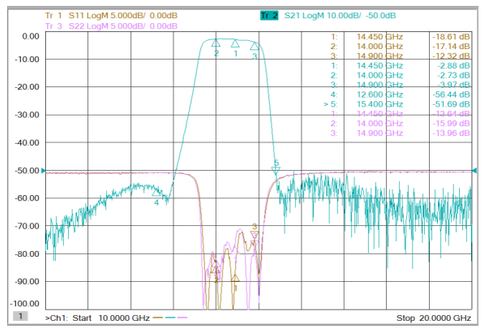
Environmental Parameters

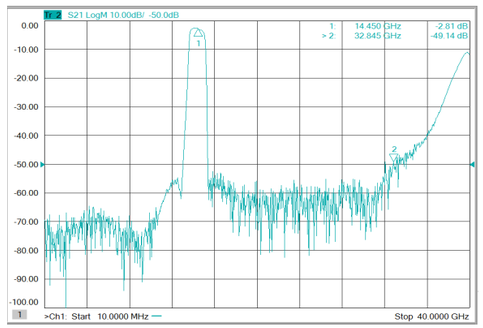
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	14.45	-	GHz
Band Freq	14	-	14.9	GHz
Fc IL	-	3	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@12.6 GHz			
	⩾50dB@15.4 GHz			

Typical Curve





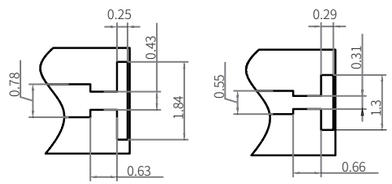
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

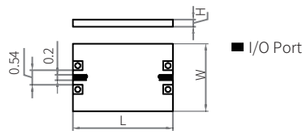


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

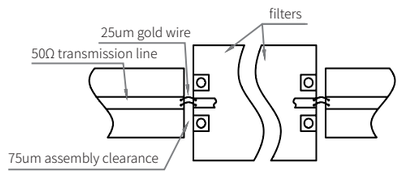
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	8.5	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB14500-7000-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

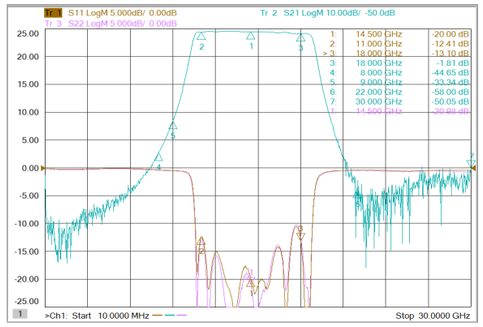
Environmental Parameters

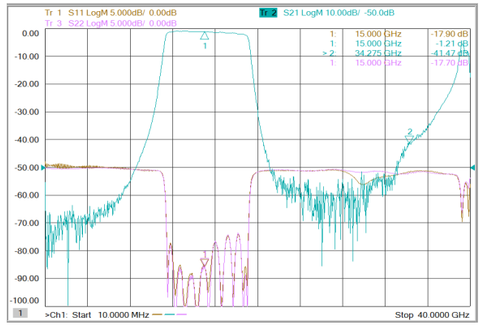
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

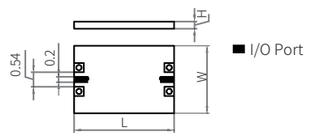
	Min	Typical	Max	
Center Freq	-	14.5	-	GHz
Band Freq	11	-	18	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	0.8	dB
VSWR	-	1.8	-	-
Rejection	⩾30dB@8 GHz			
	⩾35dB@22 GHz			

Typical Curve



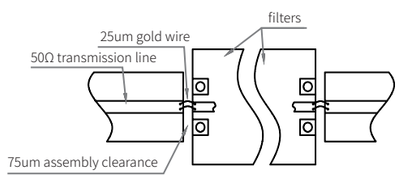


Overall Dimensions



notation	value	unit
L	7.5	mm
W	2.5	mm
H	0.381	mm

Suggested Assembly Drawings



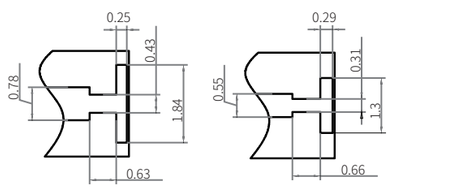
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB14700-1800-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

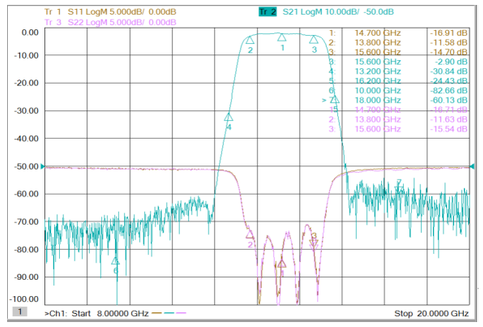
Environmental Parameters

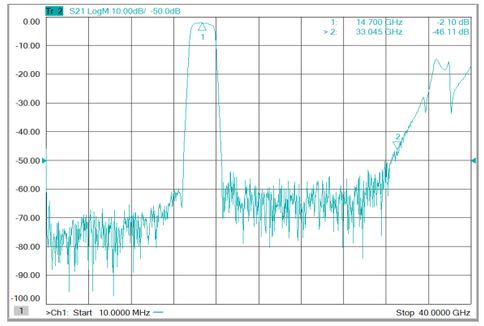
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

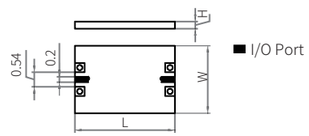
	Min	Typical	Max	
Center Freq	-	14.7	-	GHz
Band Freq	13.8	-	15.6	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.7	dB
VSWR	-	1.8	-	-
Rejection	⩾20dB@13.2 GHz			
	⩾20dB@16.2 GHz			

Typical Curve



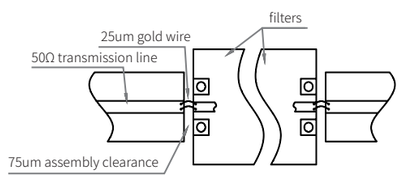


Overall Dimensions



notation	value	unit
L	7.5	mm
W	3	mm
H	0.381	mm

Suggested Assembly Drawings



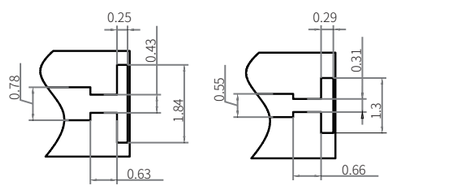
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB14750-2500-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

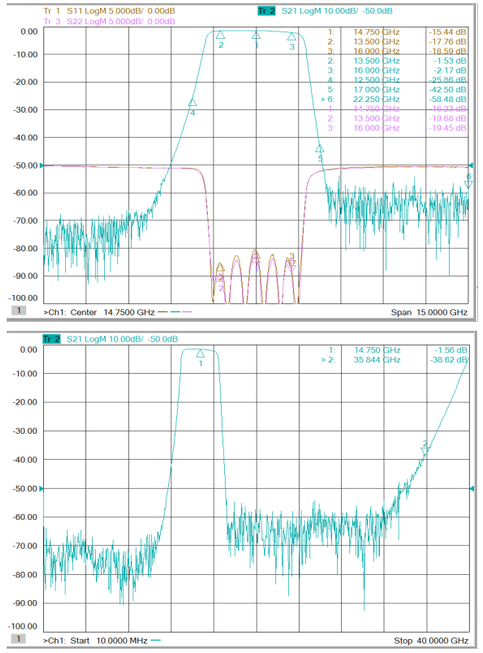
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

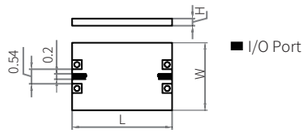
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	14.75	-	GHz
Band Freq	13.5	-	16	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	-
Rejection	⩾30dB@12.5 GHz			
	⩾30dB@17 GHz			

Typical Curve

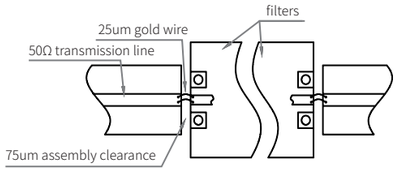


Overall Dimensions



notation	value	unit
L	8.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



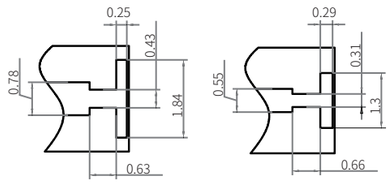
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB14900-1050-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

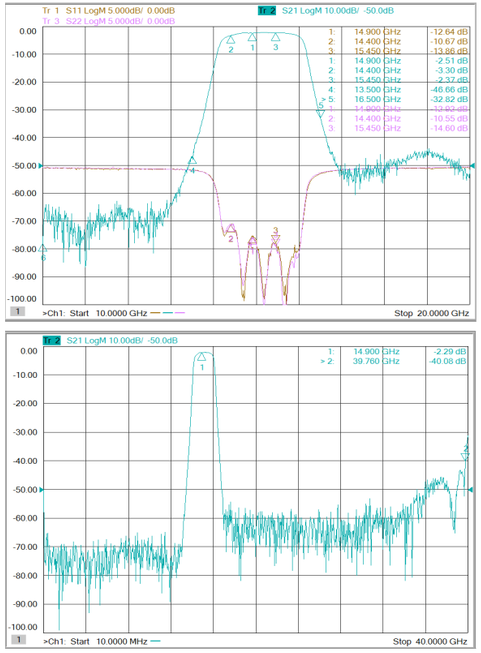
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

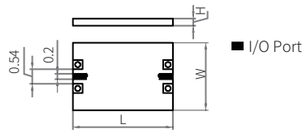
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	14.9	-	GHz
Band Freq	14.4	-	15.45	GHz
Fc IL	-	3.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@13.2 GHz			
	⩾40dB@16.85 GHz			

Typical Curve

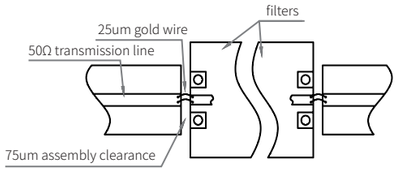


Overall Dimensions



notation	value	unit
L	7	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



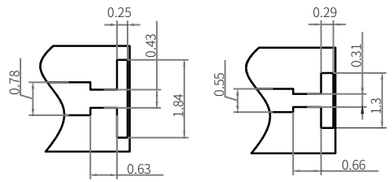
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB15000-2000-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

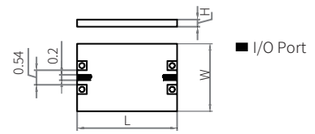
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

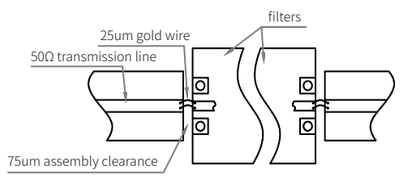
	Min	Typical	Max	
Center Freq	-	15	-	GHz
Band Freq	14	-	16	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@7.5 GHz			
	⩾50dB@22.5 GHz			

Overall Dimensions

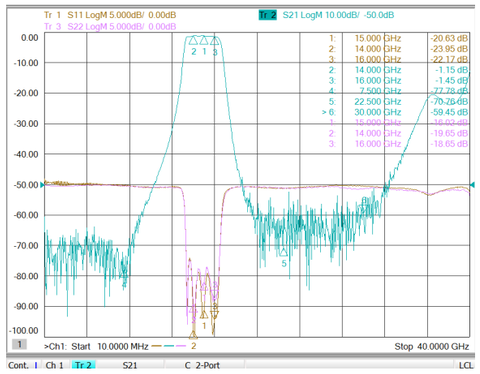


notation	value	unit
L	7	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



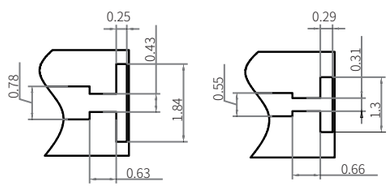
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB15000-2500-7

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

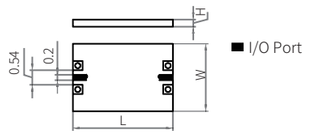
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

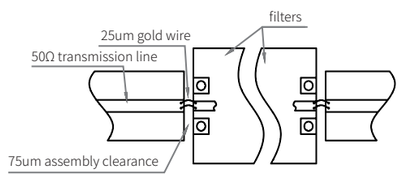
	Min	Typical	Max	
Center Freq	-	15	-	GHz
Band Freq	13.75	-	16.25	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@11GHz			
	⩾45dB@19 GHz			

Overall Dimensions

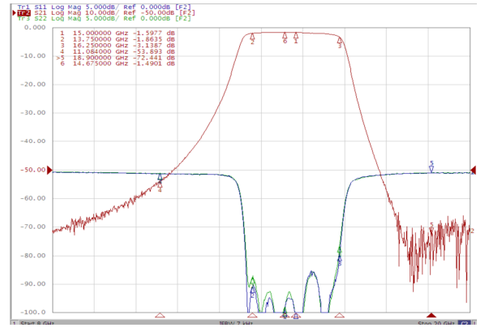


notation	value	unit
L	7.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



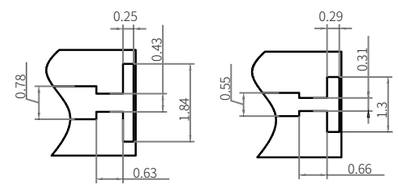
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB15000-6500-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

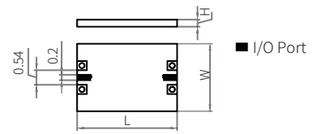
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

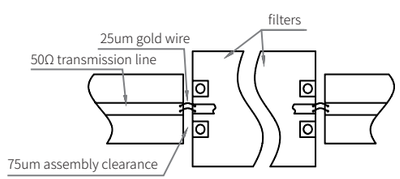
	Min	Typical	Max	
Center Freq	-	15	-	GHz
Band Freq	11.75	-	18.25	GHz
Fc IL	-	1.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@DC~8.2 GHz			
	⩾60dB@21.5~28 GHz			

Overall Dimensions

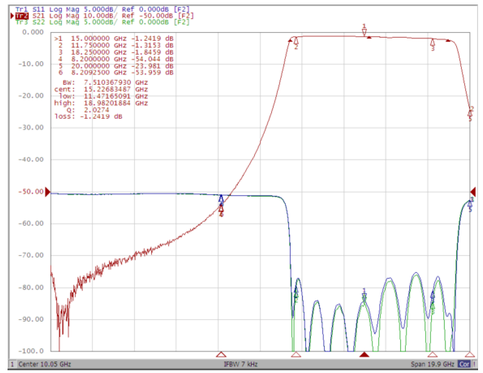


notation	value	unit
L	7.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



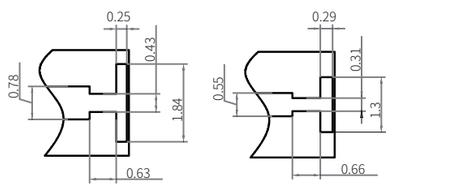
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB15500-3400-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

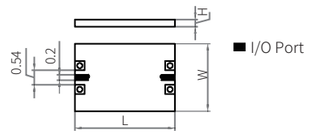
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

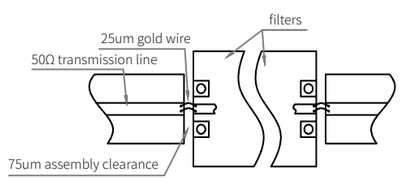
	Min	Typical	Max	
Center Freq	-	15.5	-	GHz
Band Freq	13.8	-	17.2	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@9 GHz			
	⩾60dB@21 GHz			

Overall Dimensions

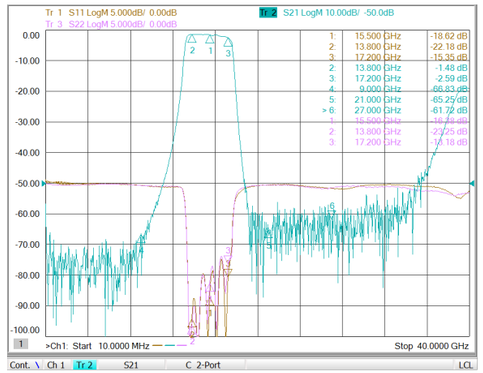


notation	value	unit
L	6.5	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



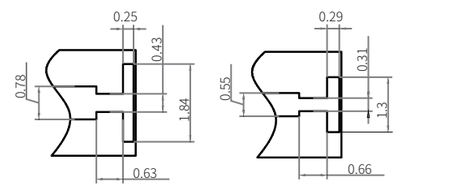
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB15750-4500-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

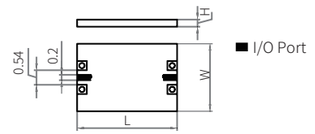
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

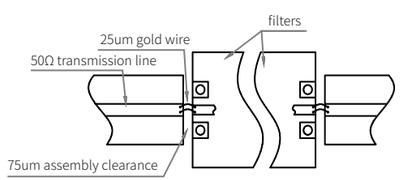
	Min	Typical	Max	
Center Freq	-	15.75	-	GHz
Band Freq	13.5	-	18	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾55dB@9GHz			
	⩾50dB@20.5 GHz			

Overall Dimensions

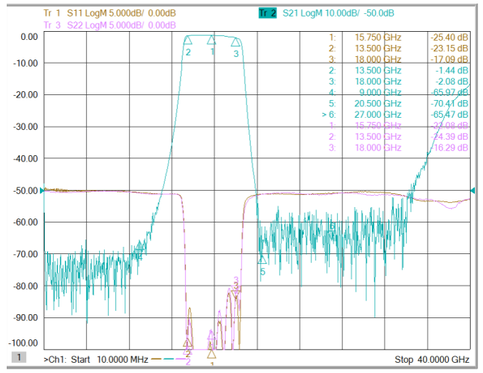


notation	value	unit
L	7.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



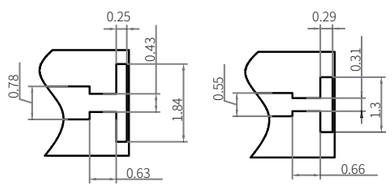
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB16000-4000-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

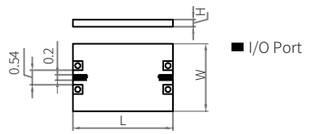
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

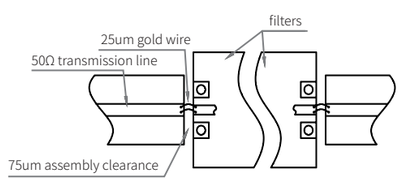
	Min	Typical	Max	
Center Freq	-	16.0	-	GHz
Band Freq	14	-	18	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾20dB@13 GHz			
	⩾20dB@19 GHz			

Overall Dimensions

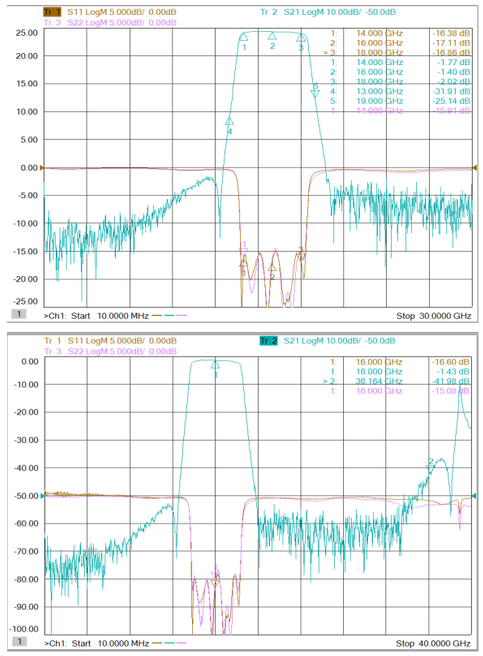


notation	value	unit
L	8.0	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



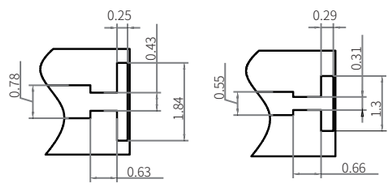
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB16155-980-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

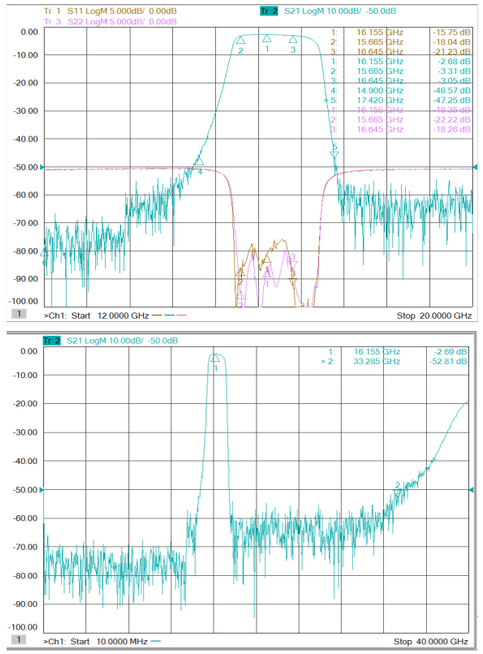
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

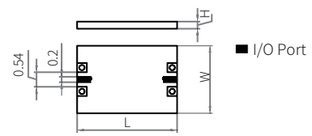
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	16.155	-	GHz
Band Freq	15.71	-	16.69	GHz
Fc IL	-	3.0	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@14.9 GHz			
	⩾40dB@17.4 GHz			

Typical Curve

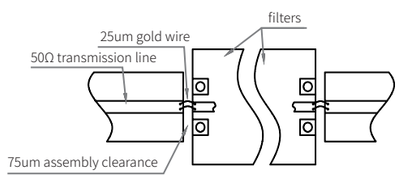


Overall Dimensions



notation	value	unit
L	8.5	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



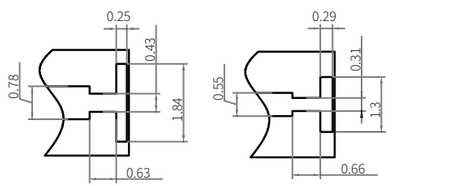
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB16500-3500-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

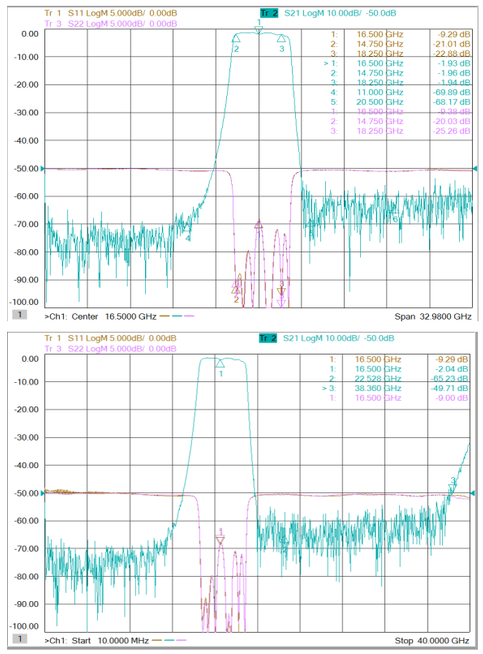
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

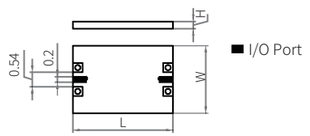
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	16.5	-	GHz
Band Freq	14.75	-	18.25	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@11GHz			
	⩾50dB@20.5 GHz			

Typical Curve

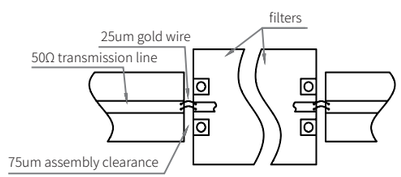


Overall Dimensions



notation	value	unit
L	8.0	mm
W	2.7	mm
H	0.254	mm

Suggested Assembly Drawings



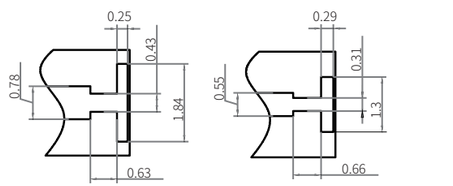
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB16500-7000-12

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

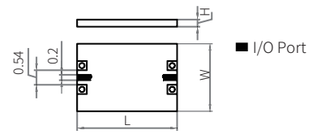
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

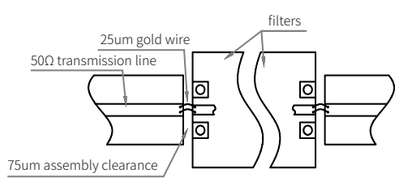
	Min	Typical	Max	
Center Freq	-	16.5	-	GHz
Band Freq	13	-	20	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@10GHz			
	⩾50dB@22.3 GHz			

Overall Dimensions

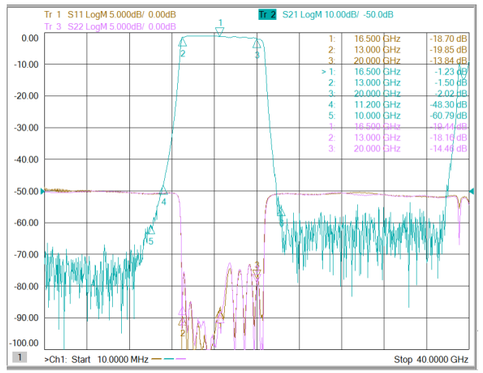


notation	value	unit
L	9.5	mm
W	3	mm
H	0.381	mm

Suggested Assembly Drawings



Typical Curve



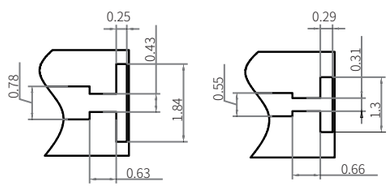
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB16650-4800-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

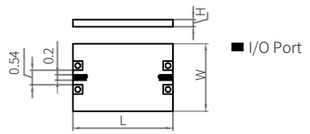
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

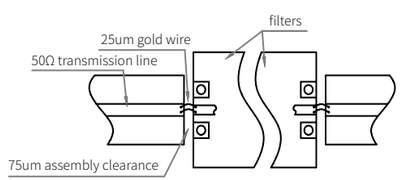
	Min	Typical	Max	
Center Freq	-	16.65	-	GHz
Band Freq	14.3	-	19.1	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@11GHz			
	⩾40dB@20.5 GHz			

Overall Dimensions

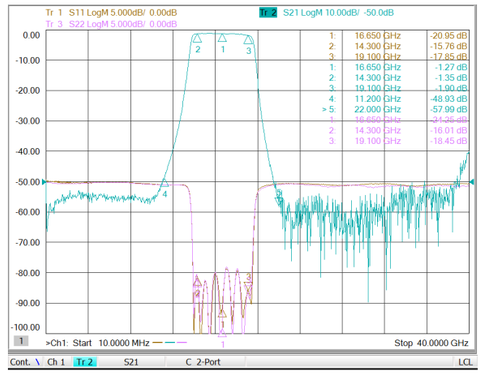


notation	value	unit
L	6	mm
W	2.7	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



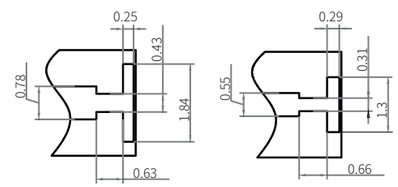
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB16975-2450-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

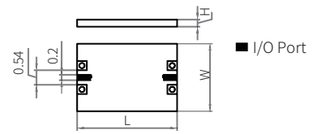
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

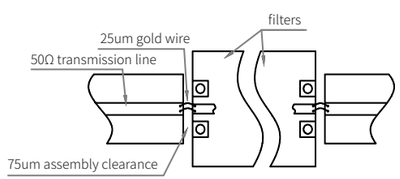
	Min	Typical	Max	
Center Freq	-	16.975	-	GHz
Band Freq	15.75	-	18.2	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@13GHz			
	⩾50dB@20 GHz			

Overall Dimensions

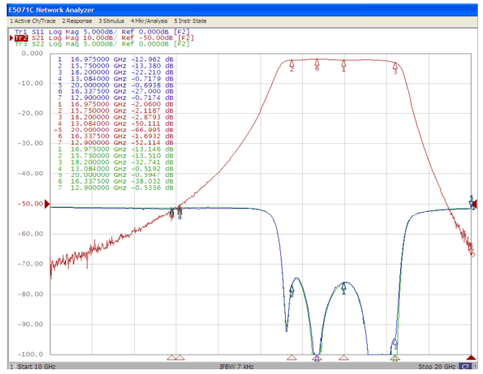


notation	value	unit
L	7.0	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



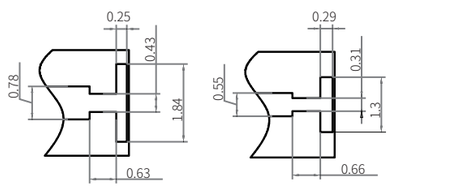
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB17250-4500-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

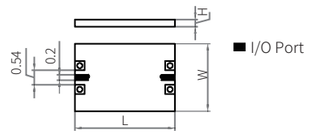
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

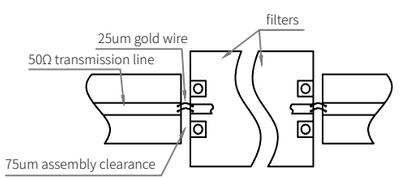
	Min	Typical	Max	
Center Freq	-	17.25	-	GHz
Band Freq	15	-	19.5	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@12GHz			
	⩾40dB@23GHz			

Overall Dimensions

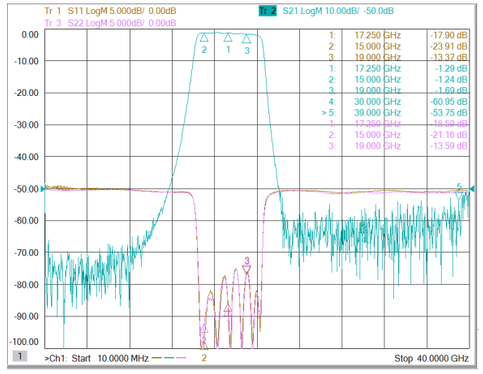


notation	value	unit
L	5.6	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



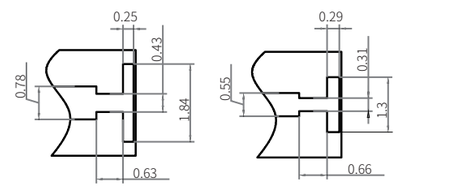
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB17350-2700-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

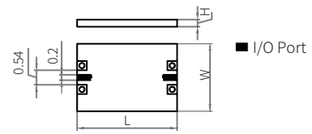
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

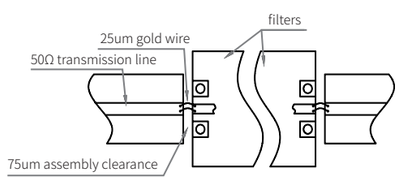
	Min	Typical	Max	
Center Freq	-	17.35	-	GHz
Band Freq	16	-	18.7	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾35dB@15GHz			
	⩾35dB@19.5GHz			

Overall Dimensions

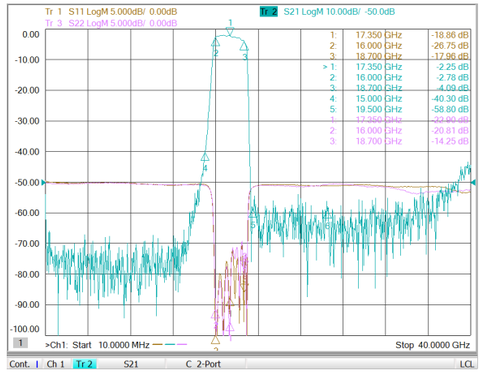


notation	value	unit
L	8	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



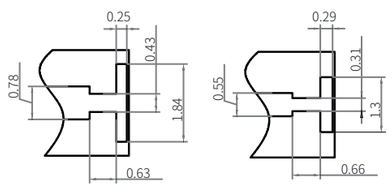
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB17875-4250-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

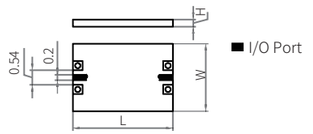
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

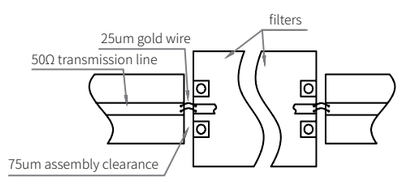
	Min	Typical	Max	
Center Freq	-	17.875	-	GHz
Band Freq	15.75	-	20	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@12.5GHz			
	⩾40dB@23.5GHz			

Overall Dimensions

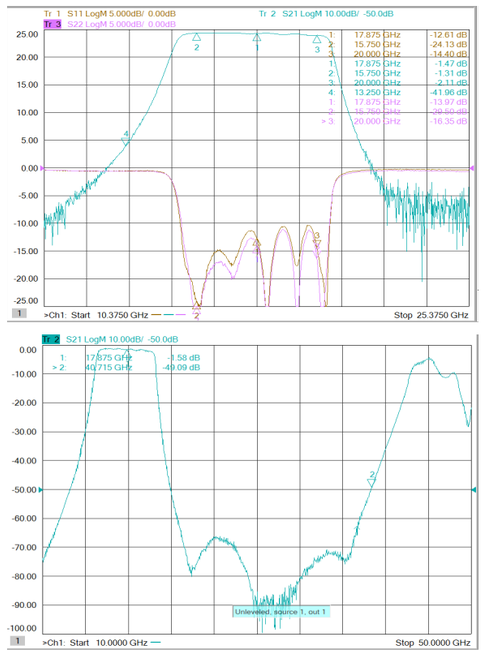


notation	value	unit
L	6.5	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



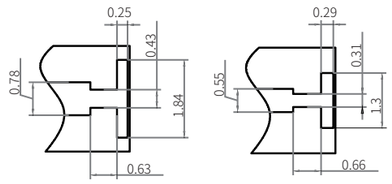
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB18000-4000-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

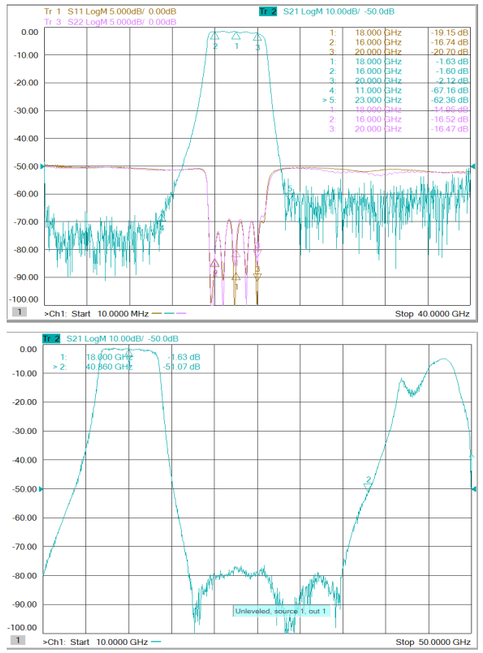
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

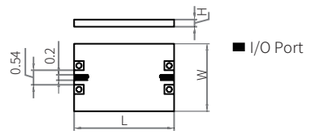
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	18	-	GHz
Band Freq	16		20	GHz
Fc IL	-	2	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8		-
Rejection	⩾45dB@11 GHz			
	⩾45dB@23 GHz			

Typical Curve

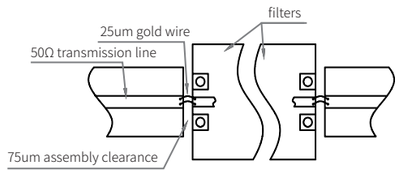


Overall Dimensions



notation	value	unit
L	6	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



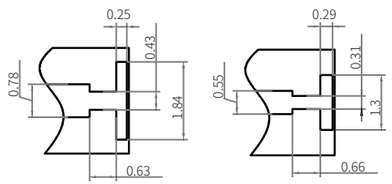
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB18000-4400-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

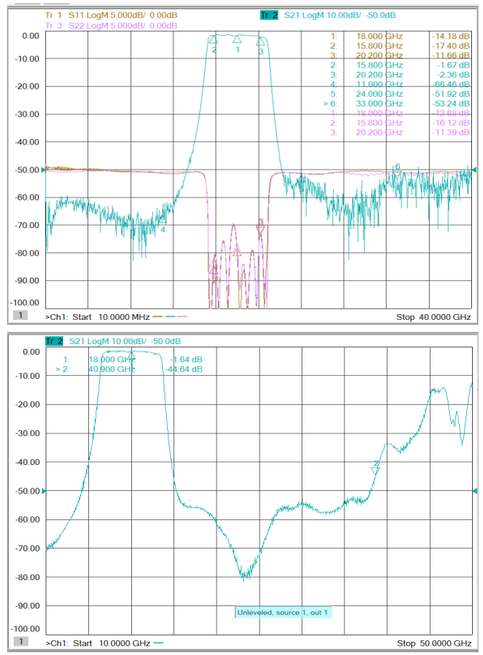
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

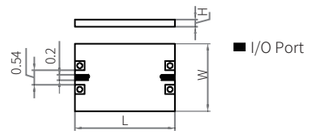
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	18	-	GHz
Band Freq	15.8	-	20.2	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@11 GHz			
	⩾50dB@24 GHz			

Typical Curve

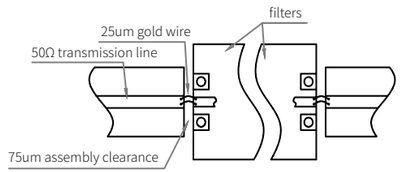


Overall Dimensions



notation	value	unit
L	8.0	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



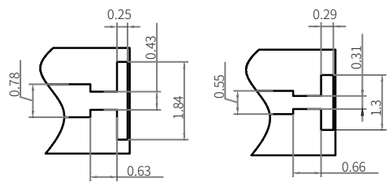
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB18500-3400-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

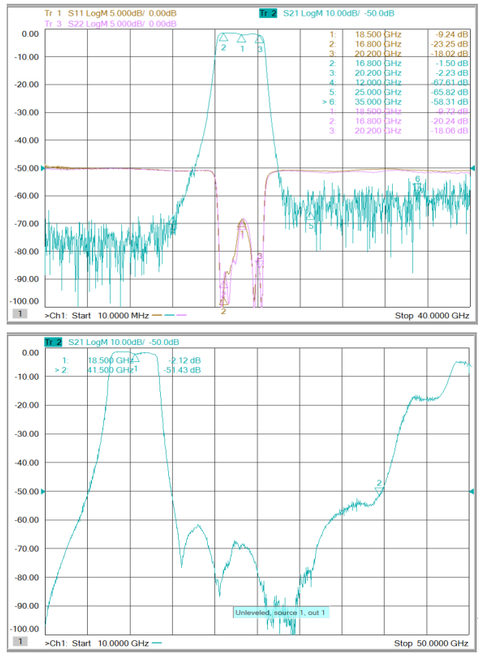
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	18.5	-	GHz
Band Freq	16.8	-	20.2	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@12 GHz			
	⩾60dB@25 GHz			

Typical Curve



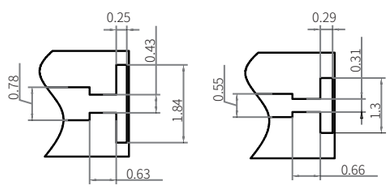
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

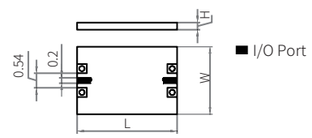


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

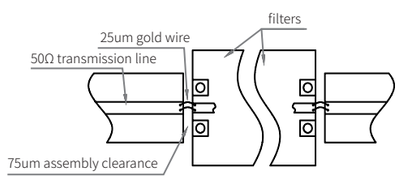
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	6.5	mm
W	2.2	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB19000-2300-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

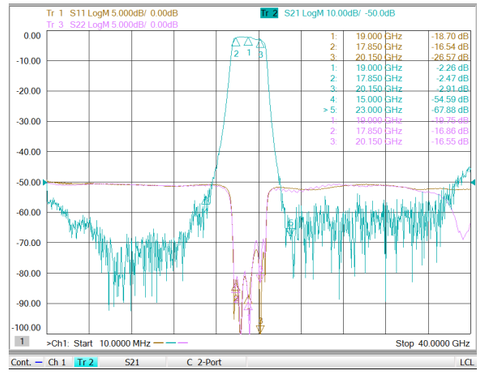
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	19	-	GHz
Band Freq	17.85	-	20.15	GHz
Fc IL	-	3	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾46dB@15 GHz			
	⩾46dB@23 GHz			

Typical Curve



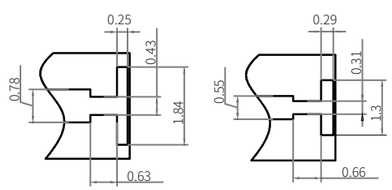
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

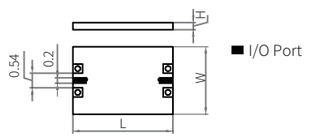


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

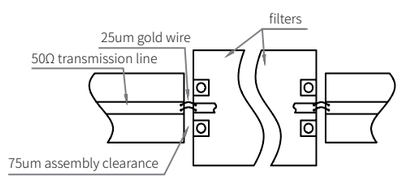
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB20328.4-20-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

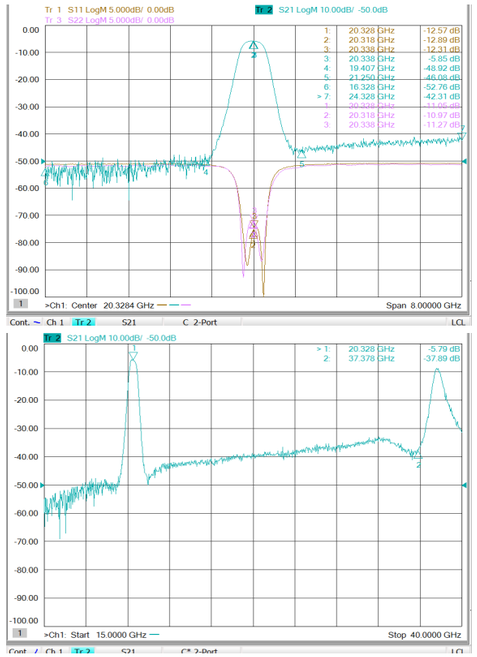
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

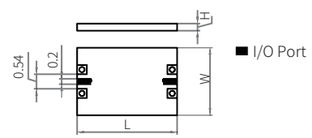
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	20.3284	-	GHz
Band Freq	20.3184	-	20.3384	GHz
Fc IL	-	6	-	dB
Passband Ripple	-	-	0.5	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@19.4068 GHz			
	⩾40dB@21.25 GHz			

Typical Curve

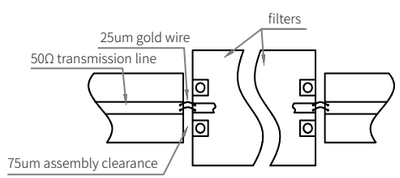


Overall Dimensions



notation	value	unit
L	3.8	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



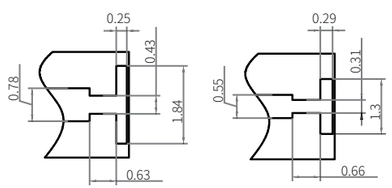
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB20500-7000-11

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

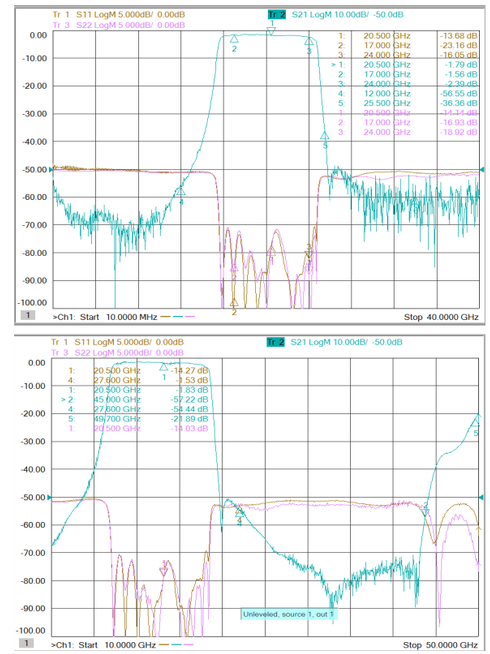
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

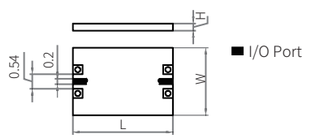
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	20.5	-	GHz
Band Freq	17	-	24	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@12GHz			
	⩾35dB@25.5GHz			

Typical Curve

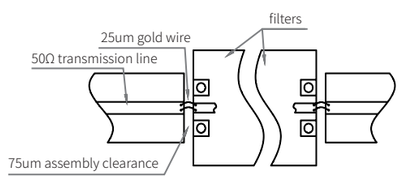


Overall Dimensions



notation	value	unit
L	7.0	mm
W	2.0	mm
H	0.254	mm

Suggested Assembly Drawings



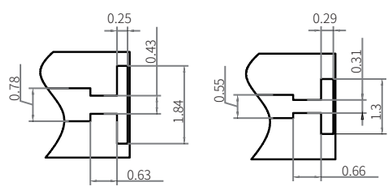
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB20750-6500-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

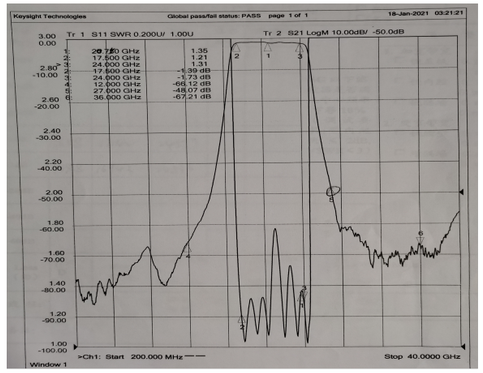
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	20.75	-	GHz
Band Freq	17.5	-	24	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@12GHz			
	⩾40dB@27GHz			

Typical Curve



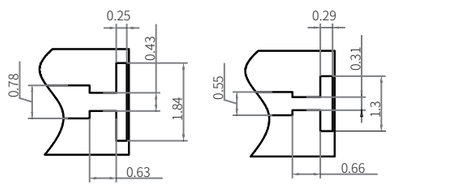
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

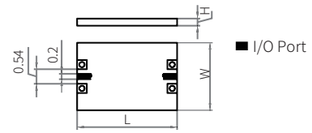


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

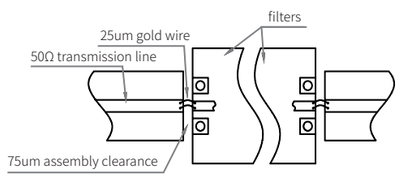
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	6.5	mm
W	2.2	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB20828.4-20-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

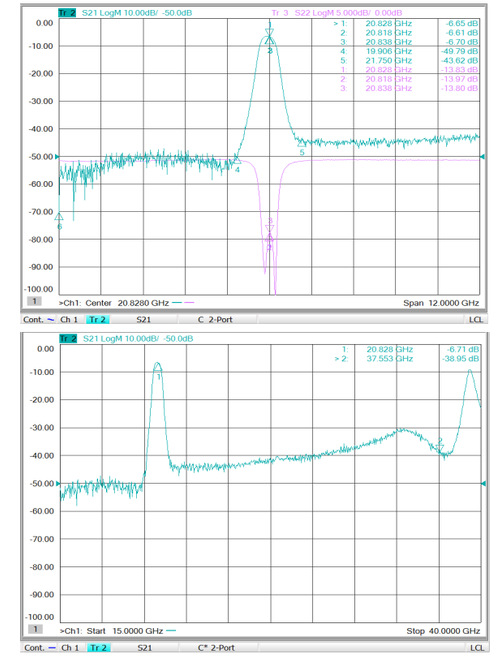
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	20.8284	-	GHz
Band Freq	20.8184	-	20.8384	GHz
Fc IL	-	7.0	-	dB
Passband Ripple	-	-	0.5	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@19.9068 GHz			
	⩾40dB@21.75 GHz			

Typical Curve



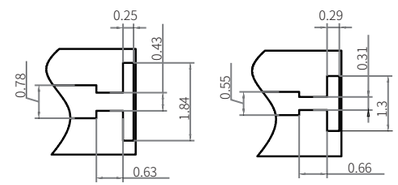
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

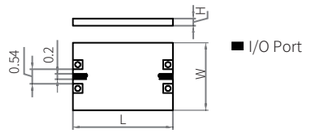


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

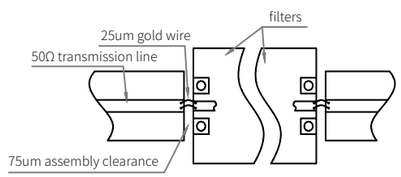
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	3.8	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB21900-1600-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

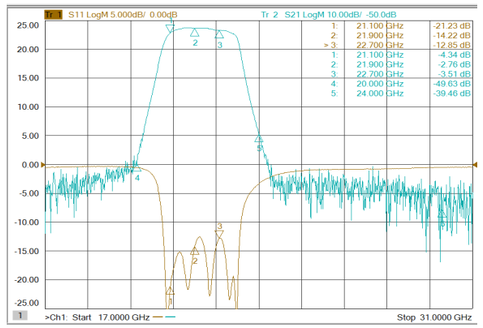
Environmental Parameters

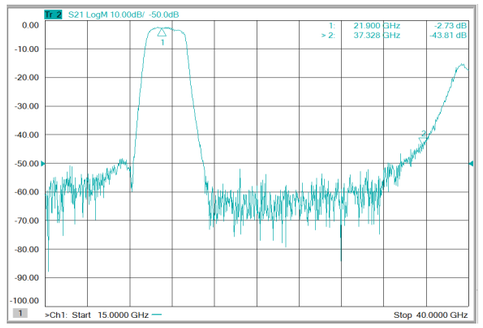
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

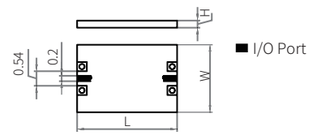
	Min	Typical	Max	
Center Freq	-	21.9	-	GHz
Band Freq	21.1	-	22.7	GHz
Fc IL	-	3.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾35dB@20GHz			
	⩾35dB@24GHz			

Typical Curve



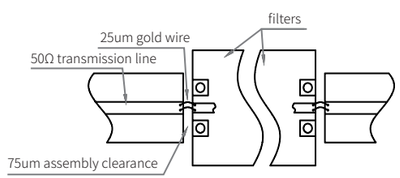


Overall Dimensions



notation	value	unit
L	9.5	mm
W	3.2	mm
H	0.254	mm

Suggested Assembly Drawings



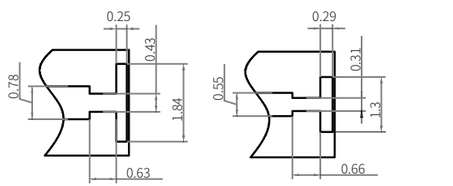
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB22000-4400-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

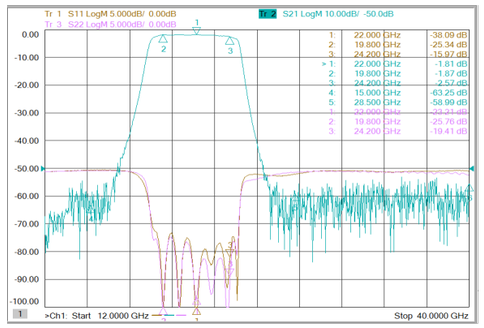
Environmental Parameters

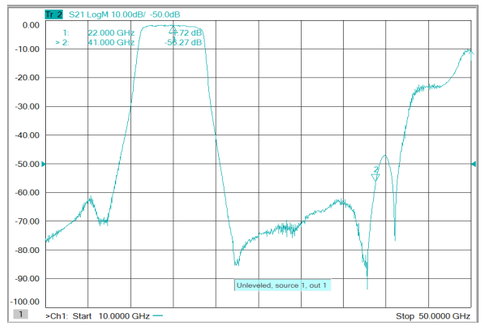
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

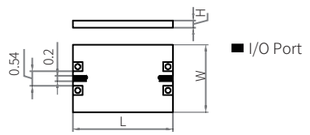
	Min	Typical	Max	
Center Freq	-	22	-	GHz
Band Freq	19.8	-	24.2	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@15GHz			
	⩾50dB@28.5GHz			

Typical Curve



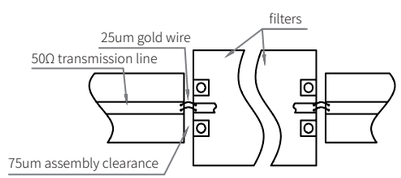


Overall Dimensions



notation	value	unit
L	7.5	mm
W	2.0	mm
H	0.254	mm

Suggested Assembly Drawings



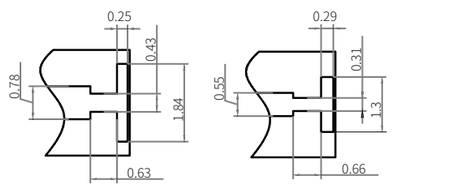
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB20750-6500-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

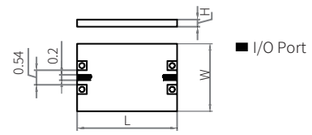
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

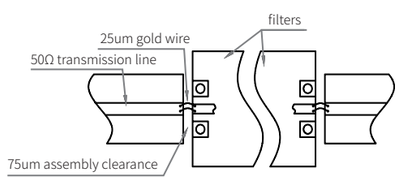
	Min	Typical	Max	
Center Freq	-	20.75	-	GHz
Band Freq	17.5	-	24	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@12GHz			
	⩾40dB@27GHz			

Overall Dimensions

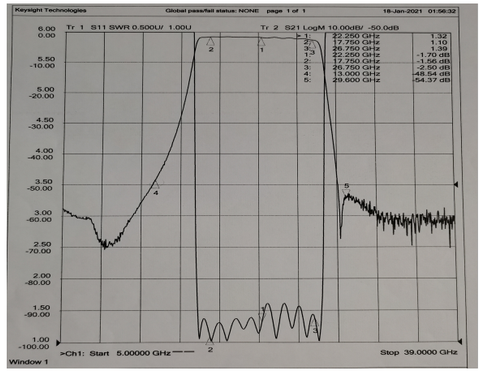


notation	value	unit
L	6.5	mm
W	2.2	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



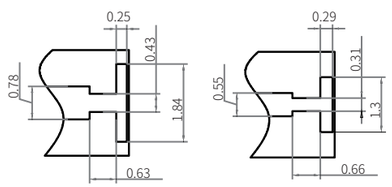
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB22250-9000-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

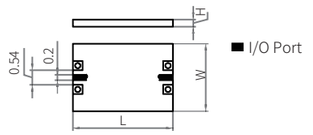
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

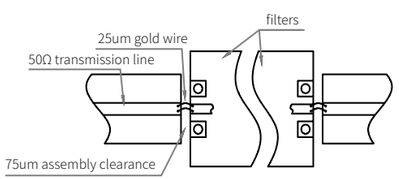
	Min	Typical	Max	
Center Freq	-	22.25	-	GHz
Band Freq	17.75	-	26.75	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@13GHz			
	⩾27dB@29.6GHz			

Overall Dimensions

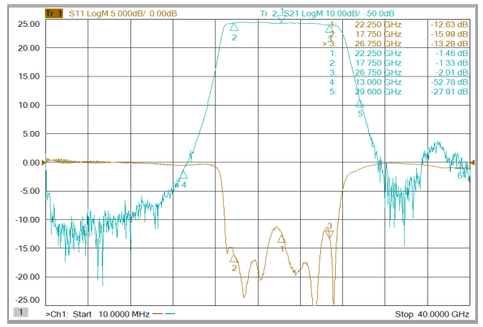


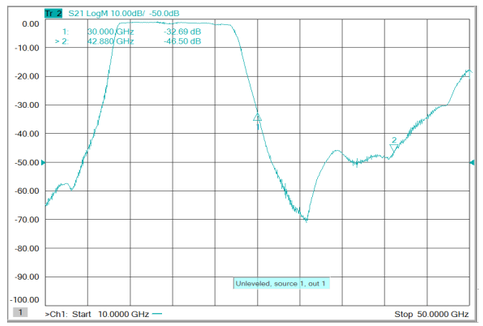
notation	value	unit
L	7	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve





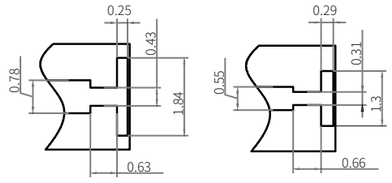
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB23171.5-20-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

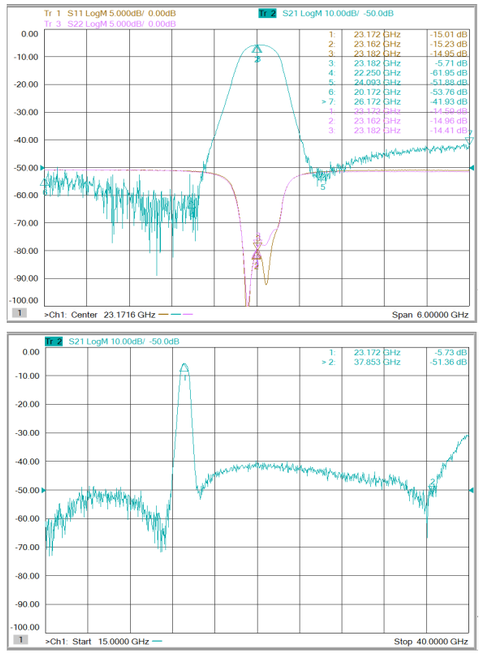
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

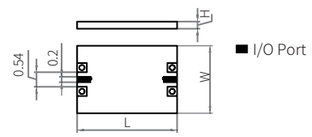
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	23.1715	-	GHz
Band Freq	23.1615	-	23.1815	GHz
Fc IL	-	6	-	dB
Passband Ripple	-	-	0.5	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@22.2499 GHz			
	⩾40dB@24.0931 GHz			

Typical Curve

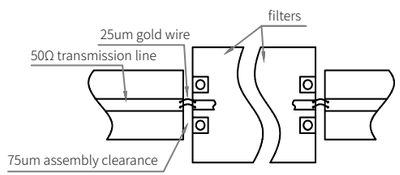


Overall Dimensions



notation	value	unit
L	3.8	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



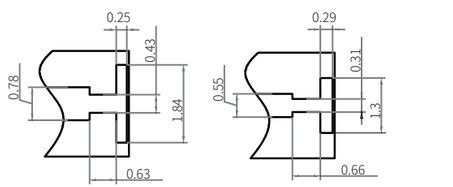
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB23200-100-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

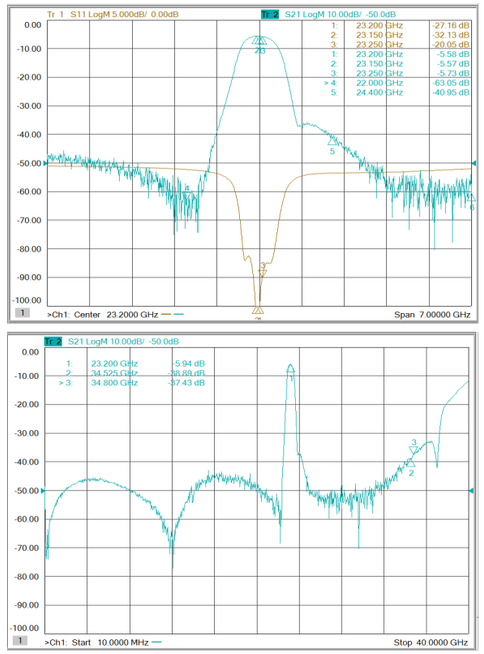
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

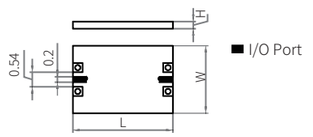
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	23.2	-	GHz
Band Freq	23.15	-	23.25	GHz
Fc IL	-	6.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@22GHz			
	⩾40dB@24.4GHz			

Typical Curve

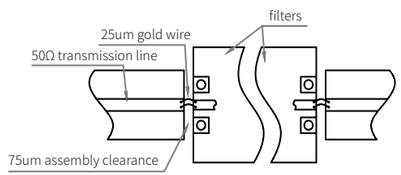


Overall Dimensions



notation	value	unit
L	4.2	mm
W	3.4	mm
H	0.254	mm

Suggested Assembly Drawings



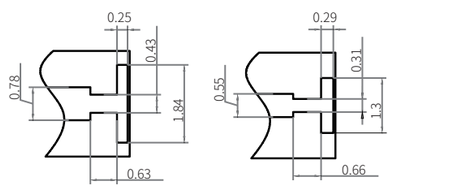
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB23671.6-20-4

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

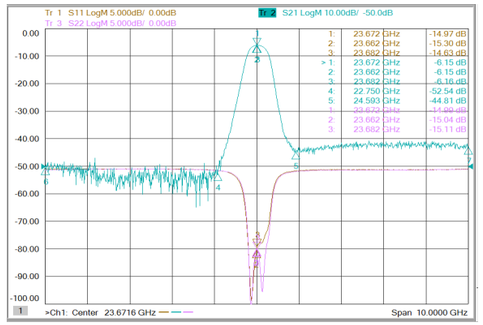
Environmental Parameters

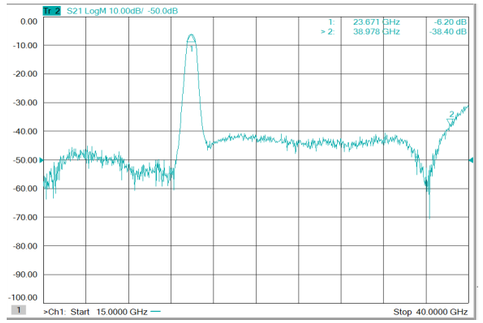
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	23.6716	-	GHz
Band Freq	23.6616	-	23.6816	GHz
Fc IL	-	6.2	-	dB
Passband Ripple	-	-	0.5	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@22.75GHz			
	⩾40dB@24.5932 GHz			

Typical Curve





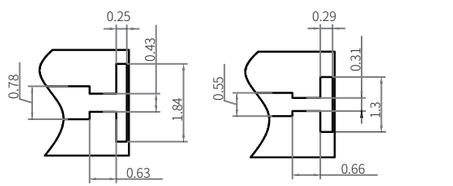
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

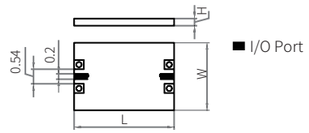


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

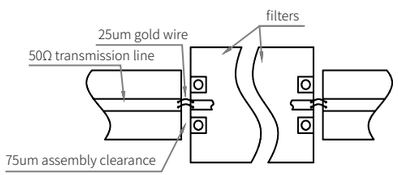
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	3.8	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB24000-1000-5

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

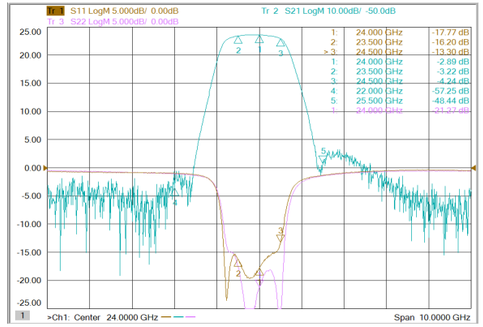
Environmental Parameters

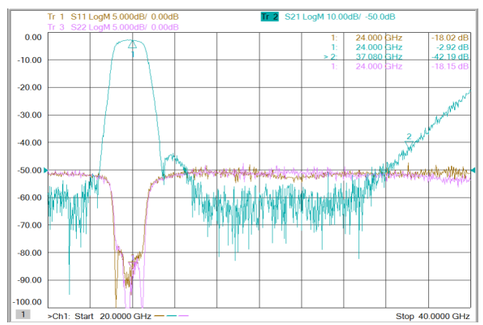
Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	24	-	GHz
Band Freq	23.5	-	24.5	GHz
Fc IL	-	3.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@22GHz			
	⩾40dB@25.5GHz			

Typical Curve





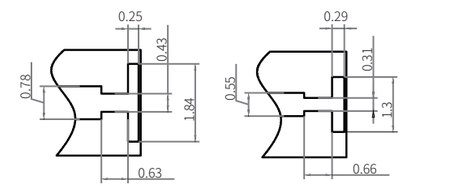
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

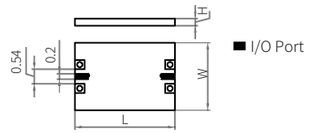


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

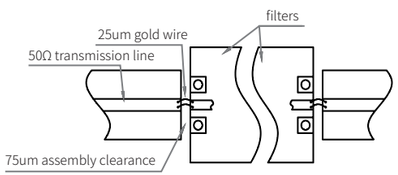
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	6.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB25000-2900-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

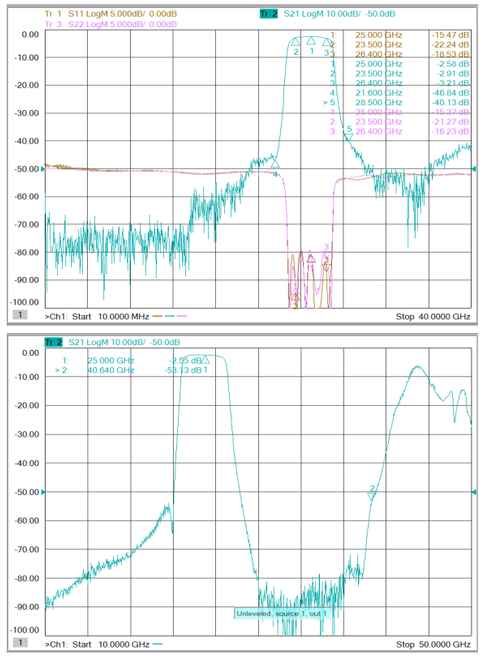
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	25	-	GHz
Band Freq	23.5	-	26.4	GHz
Fc IL	-	2.8	-	dB
Passband Ripple	-	-	1	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@21.6 GHz			
	⩾40dB@28.5 GHz			

Typical Curve



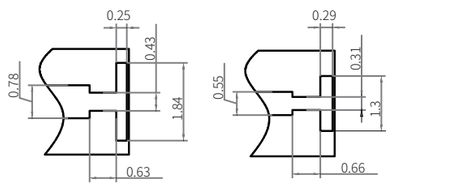
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

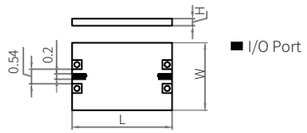


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

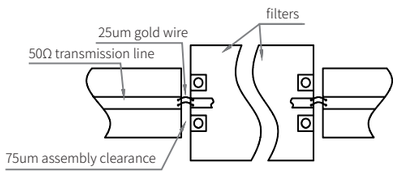
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	9.0	mm
W	3.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB26000-4400-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

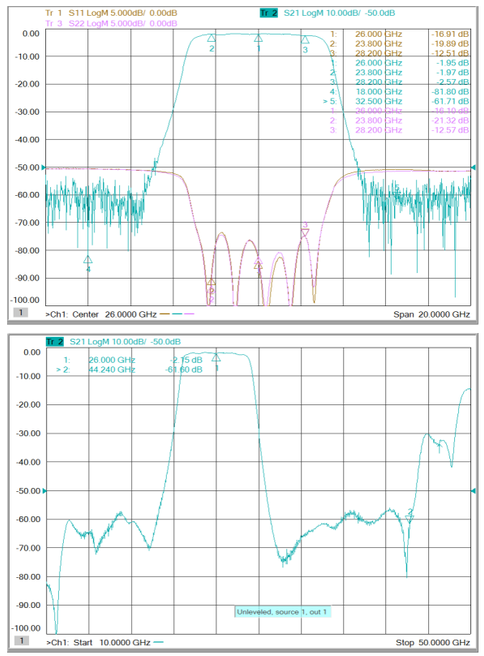
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

	Min	Typical	Max	
Center Freq	-	26	-	GHz
Band Freq	23.8	-	28.2	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾60dB@18GHz			
	⩾60dB@32.5GHz			

Typical Curve



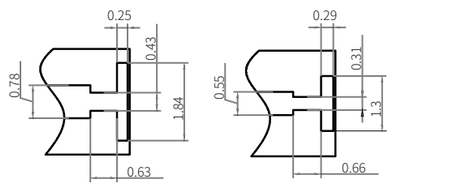
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:

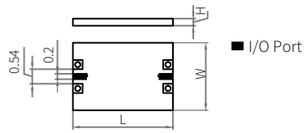


Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

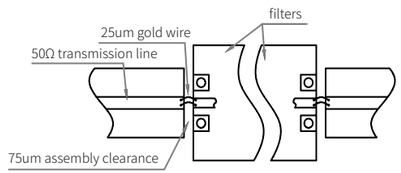
The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

Overall Dimensions



notation	value	unit
L	7.5	mm
W	2.0	mm
H	0.254	mm

Suggested Assembly Drawings



IYFTB28050-8700-9

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

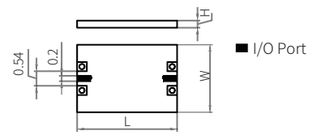
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

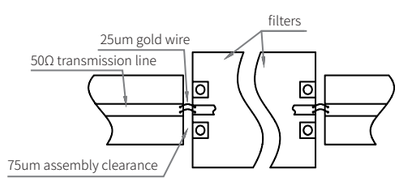
	Min	Typical	Max	
Center Freq	-	28.05	-	GHz
Band Freq	23.7	-	32.4	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@DC~16.2GHz			
	⩾35dB@35.7~45GHz			

Overall Dimensions

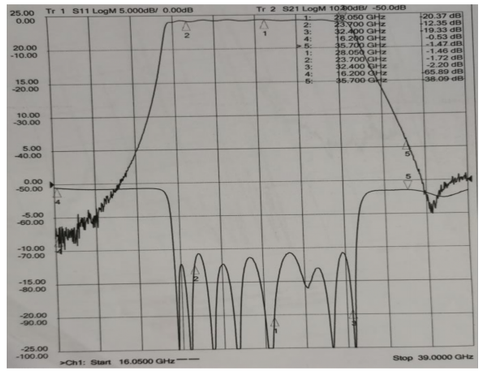


notation	value	unit
L	9.0	mm
W	2.8	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



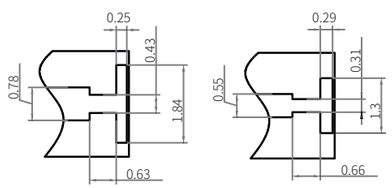
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB28500-8500-10

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

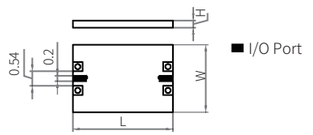
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

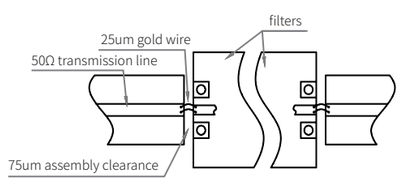
	Min	Typical	Max	
Center Freq	-	28.5	-	GHz
Band Freq	24.25		32.75	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8		-
Rejection	⩾55dB@20GHz			
	⩾50dB@37.5GHz			

Overall Dimensions

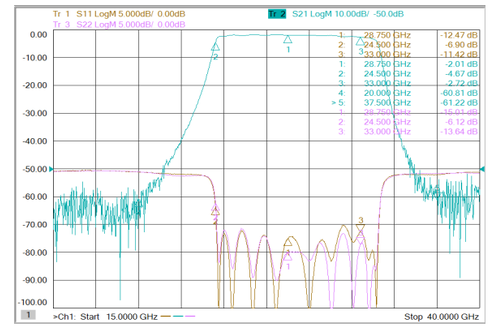


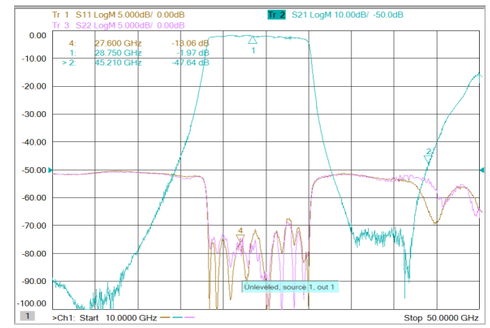
notation	value	unit
L	7.0	mm
W	2.0	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve





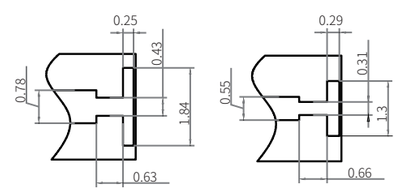
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB29000-2000-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

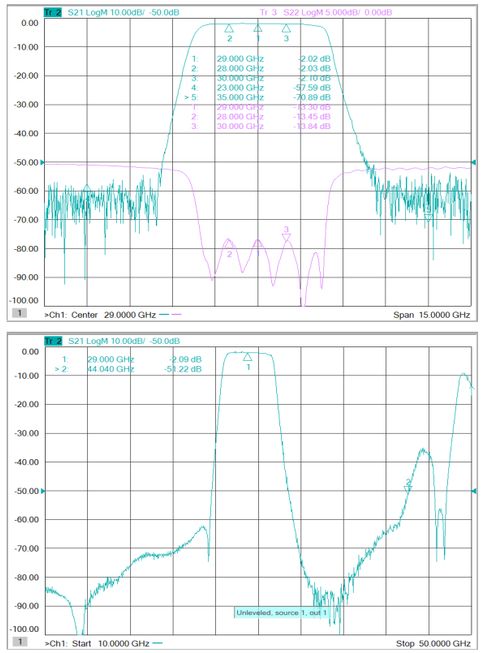
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

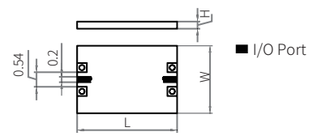
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	29	-	GHz
Band Freq	28	-	30	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@23GHz			
	⩾50dB@35GHz			

Typical Curve

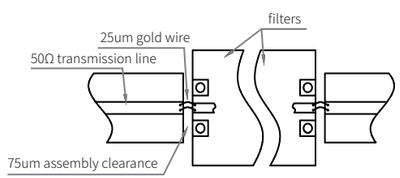


Overall Dimensions



notation	value	unit
L	9.0	mm
W	2.4	mm
H	0.254	mm

Suggested Assembly Drawings



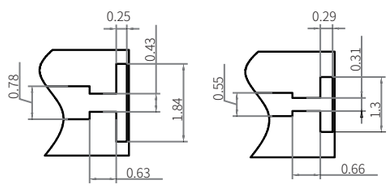
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB29000-6500-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

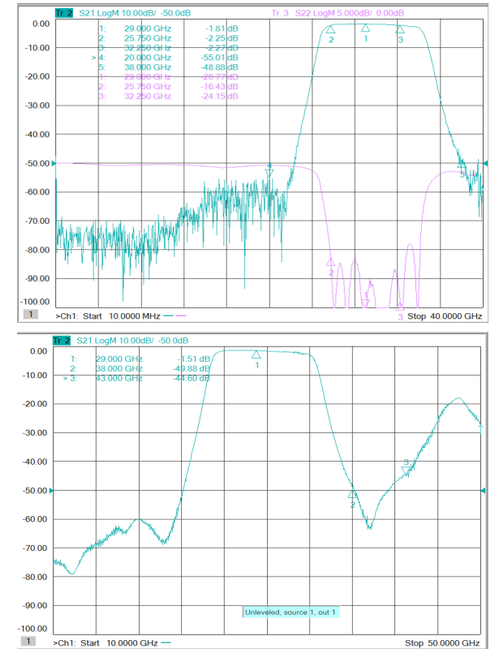
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

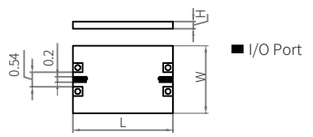
Electrical Specifications

	Min	Typical	Max	
Center Freq	-	29	-	GHz
Band Freq	25.75	-	32.25	GHz
Fc IL	-	2	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@20GHz			
	⩾45dB@38GHz			

Typical Curve

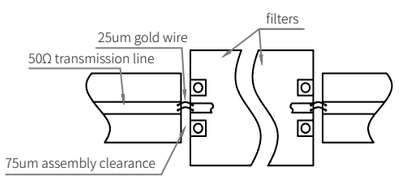


Overall Dimensions



notation	value	unit
L	8.0	mm
W	2.4	mm
H	0.254	mm

Suggested Assembly Drawings



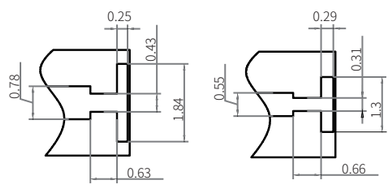
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB29500-7200-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

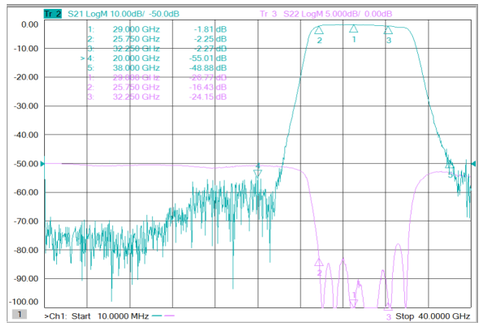
Environmental Parameters

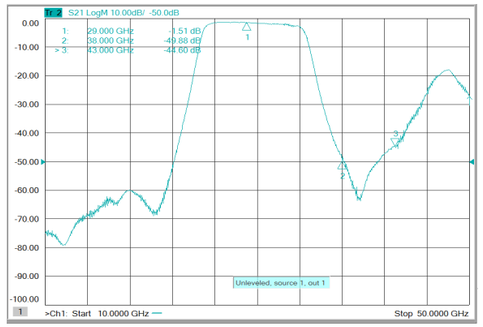
Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

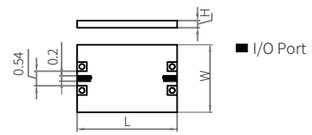
	Min	Typical	Max	
Center Freq	-	29.5	-	GHz
Band Freq	25.9	-	33.1	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@19.5GHz			
	⩾40dB@37.5GHz			

Typical Curve



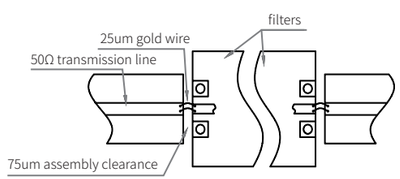


Overall Dimensions



notation	value	unit
L	7.0	mm
W	2.0	mm
H	0.254	mm

Suggested Assembly Drawings



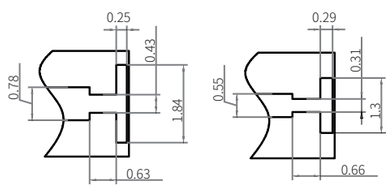
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB33000-1000-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

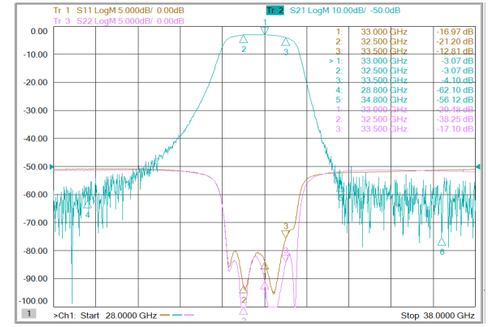
Environmental Parameters

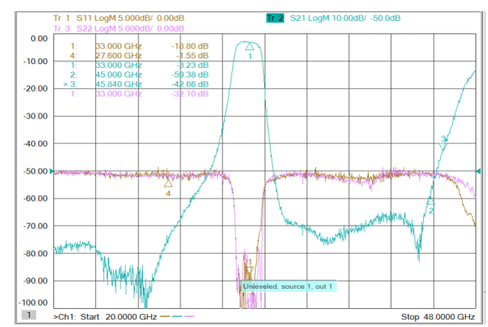
Working Temperature	-55℃~+85℃
Storage Temperature	-55℃~+125℃
Maximum Input Power	35dBm

Electrical Specifications

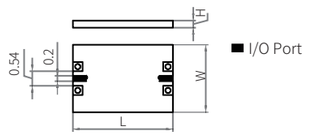
	Min	Typical	Max	
Center Freq	-	33	-	GHz
Band Freq	32..5	-	33.5	GHz
Fc IL	-	3.5	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@28.8GHz			
	⩾40dB@37.5GHz			

Typical Curve



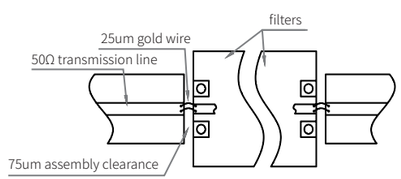


Overall Dimensions



notation	value	unit
L	7.0	mm
W	2.0	mm
H	0.254	mm

Suggested Assembly Drawings



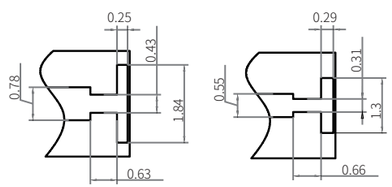
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB34000-4000-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

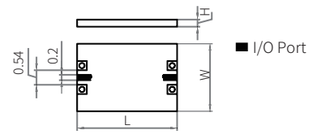
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

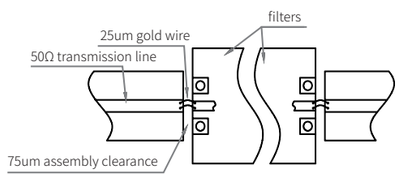
	Min	Typical	Max	
Center Freq	-	34	-	GHz
Band Freq	32	-	36	GHz
Fc IL	-	2.0	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@28 GHz			
	⩾40dB@40 GHz			

Overall Dimensions

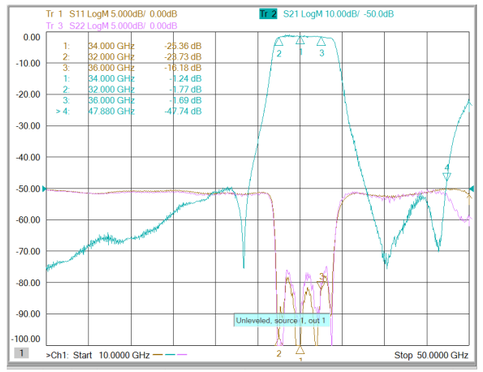


notation	value	unit
L	7.0	mm
W	2.5	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



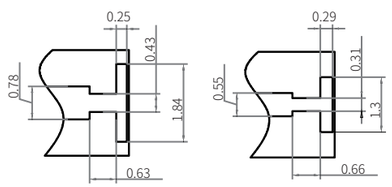
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB34150-700-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

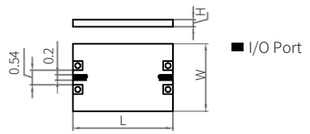
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

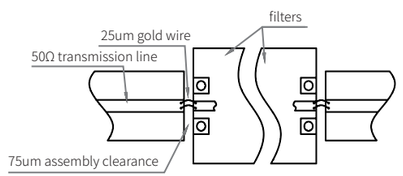
	Min	Typical	Max	
Center Freq	-	34.15	-	GHz
Band Freq	33.8	-	34.5	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@28 GHz			
	⩾50dB@40 GHz			

Overall Dimensions

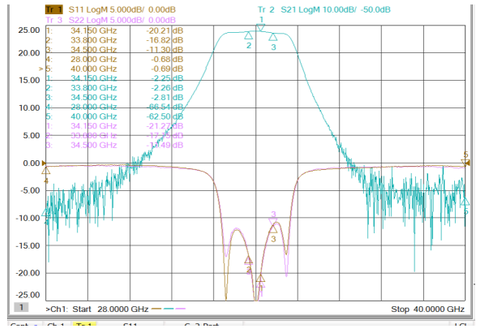


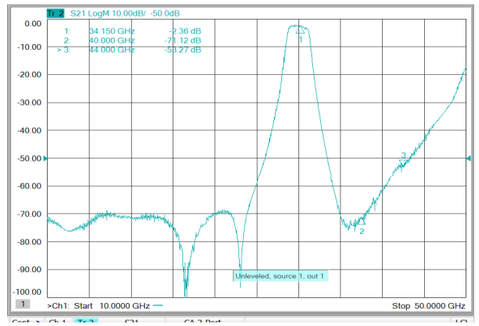
notation	value	unit
L	7	mm
W	2	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve





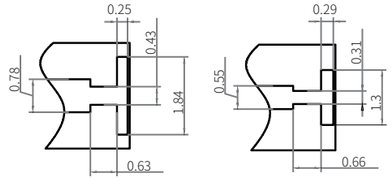
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:： DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB34500-3000-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

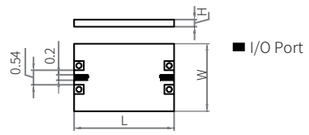
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

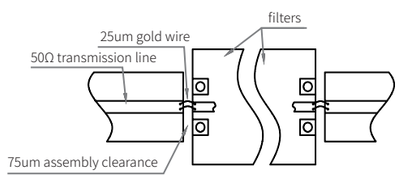
	Min	Typical	Max	
Center Freq	-	34.5	-	GHz
Band Freq	33	-	36	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	-	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@30 GHz			
	⩾50dB@38 GHz			

Overall Dimensions

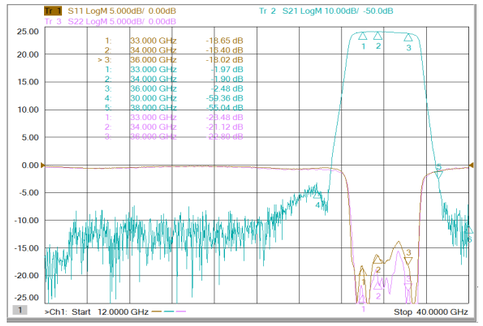


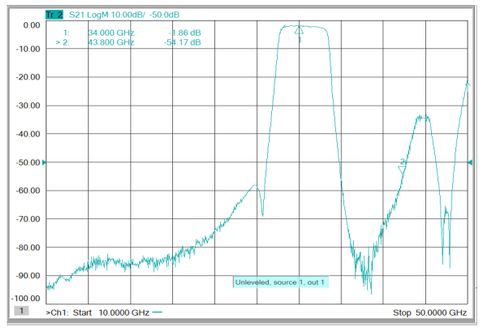
notation	value	unit
L	8.5	mm
W	2.4	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve





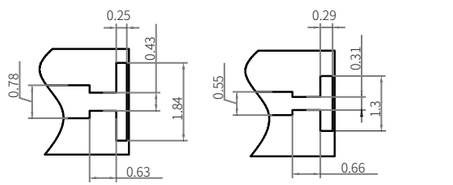
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB34500-3400-6

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

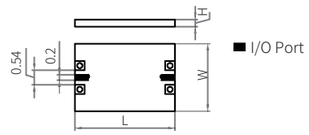
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

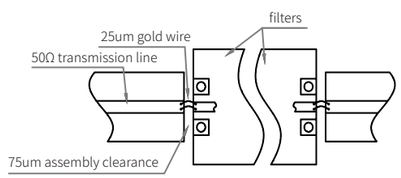
	Min	Typical	Max	
Center Freq	-	34.5	-	GHz
Band Freq	32.8	-	36.2	GHz
Fc IL	-	2	-	dB
Passband Ripple	-	-	1.0	dB
VSWR	-	1.8	-	-
Rejection	⩾40dB@29.6 GHz			
	⩾35dB@39.1 GHz			

Overall Dimensions

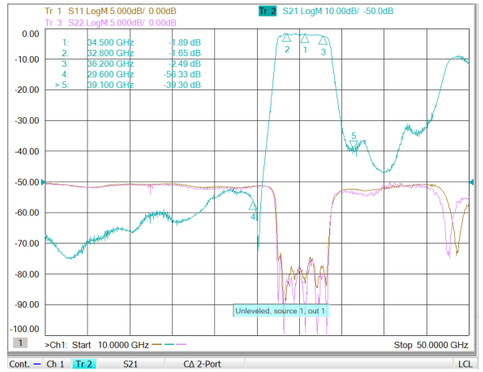


notation	value	unit
L	8	mm
W	3	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



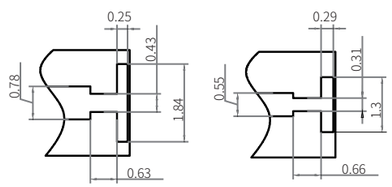
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB36000-8000-8

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

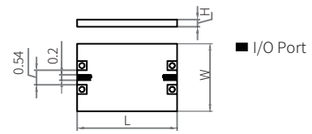
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

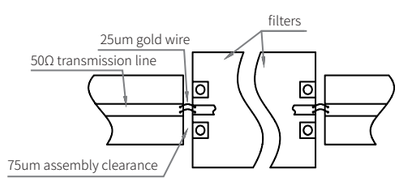
	Min	Typical	Max	
Center Freq	-	36	-	GHz
Band Freq	32	-	40	GHz
Fc IL	-	2.5	-	dB
Passband Ripple	-	-	1.5	dB
VSWR	-	1.8	-	-
Rejection	⩾45dB@21 GHz			
	⩾30dB@42 GHz			

Overall Dimensions

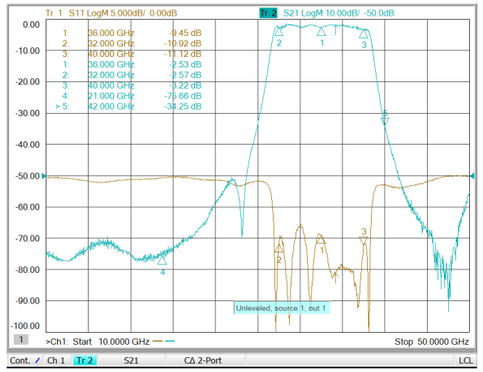


notation	value	unit
L	7.5	mm
W	2	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



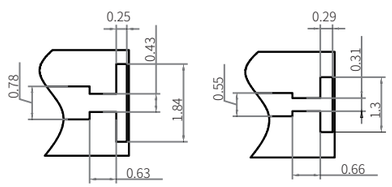
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.

IYFTB40500-600-5

Performance Characteristics

1、High precision micro-nanometer processing technology
2、High performance, low temperature drift, high power
3、Gold wire bonding, suitable for multi-chip integration module applications
4、50Ω coplanar waveguide output

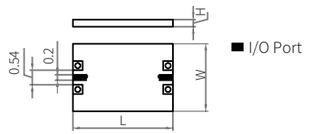
Environmental Parameters

Working Temperature	-55°C~+85°C
Storage Temperature	-55°C~+125°C
Maximum Input Power	35dBm

Electrical Specifications

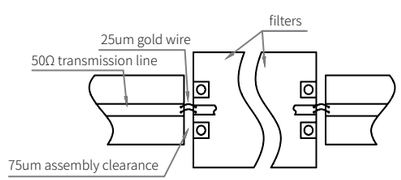
	Min	Typical	Max	
Center Freq	-	40.5	-	GHz
Band Freq	40.2	-	40.8	GHz
Fc IL	-	3	-	dB
Passband Ripple	-	-	1.2	dB
VSWR	-	1.8	-	-
Rejection	⩾50dB@31 GHz			
	⩾15dB@51 GHz			

Overall Dimensions

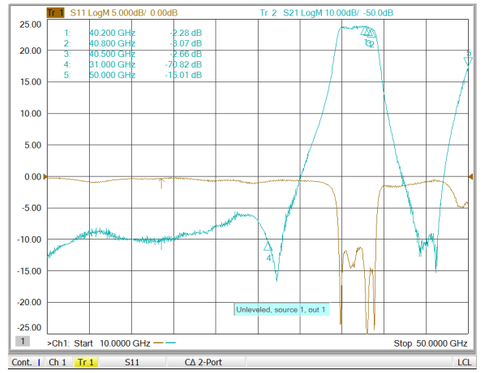


notation	value	unit
L	6	mm
W	2	mm
H	0.254	mm

Suggested Assembly Drawings



Typical Curve



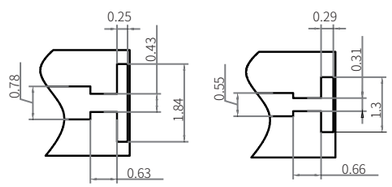
Caveat

1、It is recommended that the filter be used in separate chambers, with both sides of the filter on the upper line about 0.2mm from the wall. The upper surface of the filter is about 3mm away from the upper cover plate;

2、The filter is recommended to be bonded with low-stress conductive adhesive (such as ME8456);

3、The filter should be mounted on a carrier with a comparable coefficient of thermal expansion (6.7ppm / °C) of the substrate such as Kovar (recommended) or molybdenum-copper, and the thickness of the carrier ⩾ 0.2mm;

4、Circuit microstrip line and filter chip bonding connection, it is recommended that the microstrip line bonding to match the T-shaped structure, T-head size is as follows:



Rogers5880
Thickness: 0.254mm
Applicable frequency: DC-30GHz

Rogers4350
Thickness: 0.254mm
Applicable frequency:: DC-25GHz

The top of the T-head graphic is 50um from the edge of the substrate, and no matching is required for frequencies below 10HGHz.